8A Single Cell Smart Cap Divider and Direct Charge Charger with 8-Channel ADC, USB BC 1.2 Detection

General Description

The RT9756A is a high efficiency and high charge current charger. The efficiency is up to 98.2% when V_{BAT} = 4V, I_{BAT} = 2A and the maximum charge current is up to 8A in DIV2 mode. The efficiency is up to 99.1% when V_{BAT} = 4V, I_{BAT} = 1A and the maximum charger current is up to 5A in bypass mode. The device integrates smart cap divider topology, direct charging mode, external overvoltage protection control, an input reverse blocking NFET and 2-way regulation, a dual-phase charge pump core, 14-way protection, 9-way system alarm, 8-Channel high speed analog-to-digital converter and USB BC 1.2 detection. The high speed analog-to-digital converter provides input and output voltage, current and temperature information for the host. The host can monitor the information by I^2C serial interface.

The recommended junction temperature range is –40°C to 125°C, and the ambient temperature range is –40°C to 85°C.

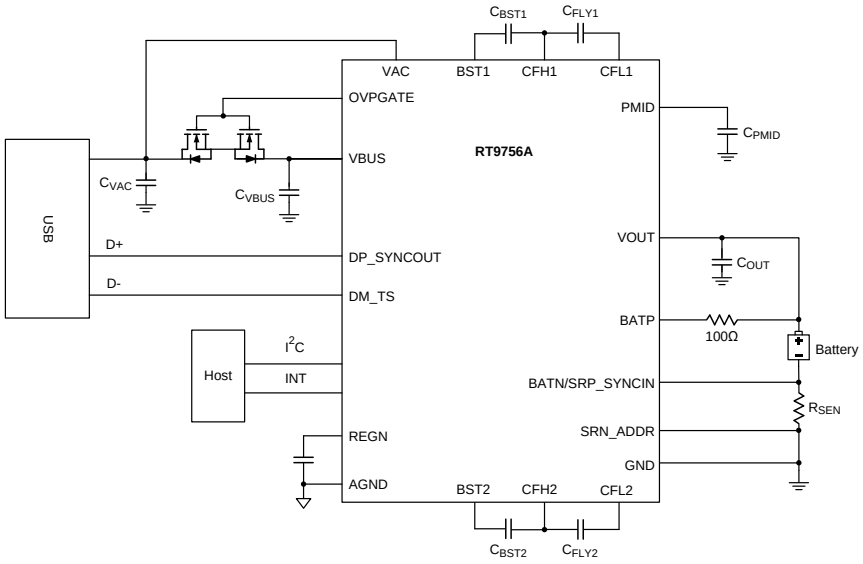
Features

- **Integrates Cap Divider Mode (DIV2 Mode) and Direct Charging Mode (Bypass Mode)**
- **Supports BC1.2**
- **External OVPMOS Control and Regulation**
  - **High Absolute Maximum Rating of 37V**
  - **Fast Reaction Time 100ns and Fast Turn Off Time 100ns**
  - **VBAT Voltage Regulation (VBAT REG)**
  - **IBAT Current Regulation (IBAT REG)**
- **Dual-Phase Charge Pump Core**
  - **8A Output Current Capability**
  - **Efficiency Up to 98.2% when V_{BAT} = 4V, I_{BAT} = 2A (DIV2 Mode)**
  - **Efficiency Up to 99.1% when V_{BAT} = 4V, I_{BAT} = 1A (Bypass Mode)**
  - **100kHz to 1000kHz Variable Switching Frequency Stay Out of Audio Band**
  - **Spread Spectrum Technology for EMI Reduction**

Applications

- Smart Phones
- Tablet

Simplified Application Circuit



- 8-Channel 12-bit ADC
  - High Speed Data Rate for 128 Times Average Per Channel
  - VBUS, IBUS, VOUT, VBAT, IBAT, TDIE, DP, DM 8-Channel for Voltage/Current/Temperature Measurement
- Input Reverse Blocking NFET
  - Block the Reverse Current
- 3-Error Charge Pump Switch Protection
  - VBUS Voltage Too High Error Protection before Switch (VBUS_HIGH_ERR)
  - VBUS Voltage Too Low Error Protection before Switch (VBUS_LOW_ERR)
  - CFLY Short Error Protection Before Switch (CFLY_DIAG)
- 11-Way System Protection
  - VAC Overvoltage Protection (VAC_OVP)
  - VBUS Overvoltage Protection (VBUS_OVP)
  - IBUS Overcurrent Protection (IBUS_OCP)
  - Higher IBUS Overcurrent Protection (IBUS_OCP_H)
  - IBUS Undercurrent Protection (IBUS_UCP)
  - VOUT Overvoltage Protection (VOUT_OVP)
  - VBAT Overvoltage Protection (VBAT_OVP)
  - IBAT Overcurrent Protection (IBAT_OCP)
  - Dropout Overvoltage Protection (VDR_OVP)
  - TS Over-Temperature Protection (TS_OTP)
  - Junction Over-Temperature Protection (TDIE_OTP)
- 9-Way System Alarm
  - VBUS Overvoltage Alarm (VBUS_OVP_ALM)
  - IBUS Overcurrent Alarm (IBUS_OCP_ALM)
  - IBUS Undercurrent Alarm (IBUS_UCP-ALM)
  - VBAT Overvoltage Alarm (VBAT_OVP_ALM)
  - IBAT Overcurrent Alarm (IBAT_OCP_ALM)
  - IBAT Undercurrent Alarm (IBAT_UCP-ALM)
  - TDIE Over-Temperature Alarm (TDIE_OTP_ALM)
  - DP Overvoltage Alarm (DP_OV_ALM)
  - DM Overvoltage Alarm (DM_OV_ALM)

Ordering Information

RT9756A □-□

- Packing
  - A: Standard
  - B: Pin 1 Orientation (Quadrant 2, Follow EIA-481)
- Package Type
  - P: WL-CSP-36B 2.8x2.8 (BSC)

Note:

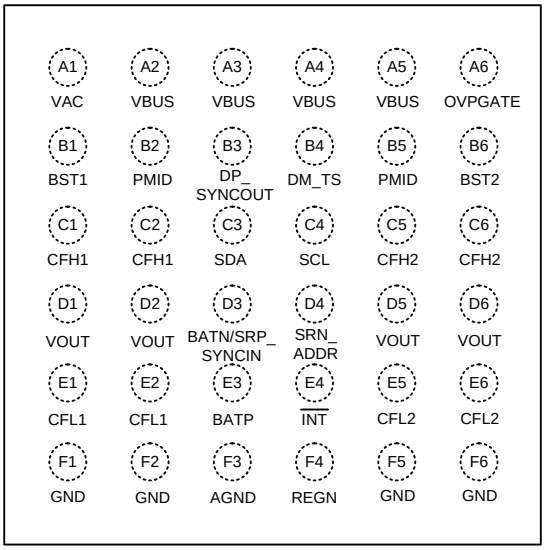
Richtek products are Richtek Green Policy compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.

Marking Information

31: Product Code
XXYY: Wafer ID with Check Sum
CCC-RRR: IC Coordinate (X, Y)
YMDNN: Date Code

Pin Configuration

(TOP VIEW)



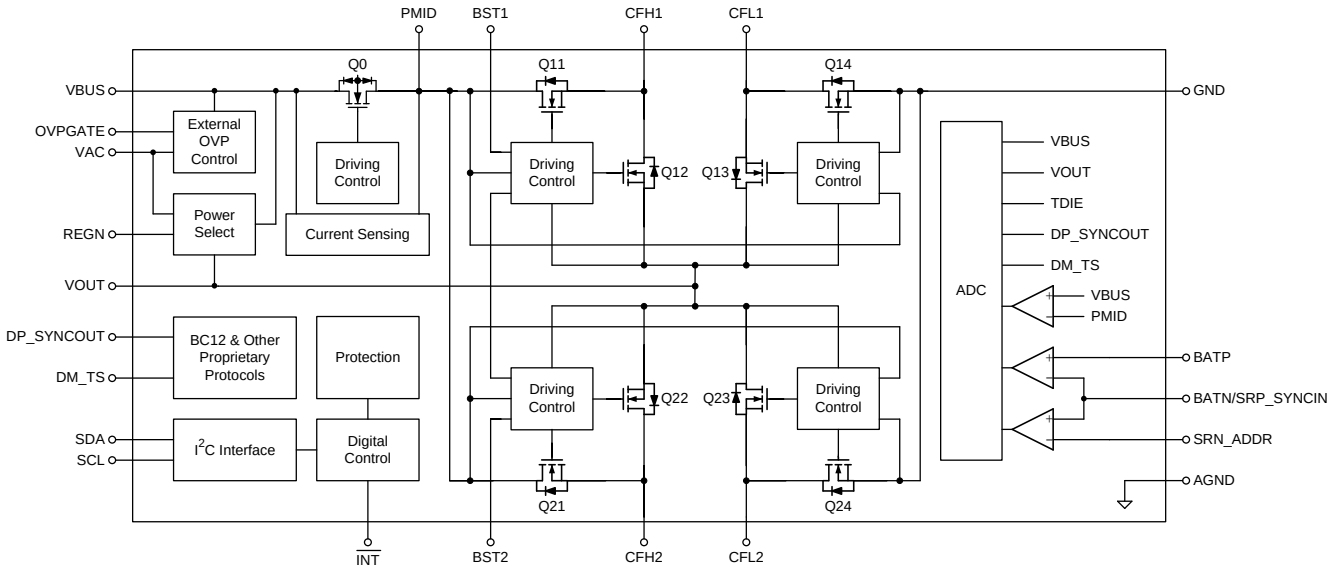
WL-CSP-36B 2.8x2.8 (BSC)

Functional Pin Description

Pin No.	Pin Name	I/O	Pin Function
A1	VAC	AI	Input voltage sense pin. Connect to VBUS if the external N-FET is not used.
A2, A3, A4, A5	VBUS	P	These pins are the input power supply and must be connected together on the PCB. One 2.2μF capacitor must be connected from VBUS to GND and placed close to these pins.
A6	OVPGATE	AO	External N-FET control pin, connect to the gate of the external N-FET.
B1	BST1	P	The high-side MOSFET driver positive supply. One 0.1μF capacitor must be connected from BST1 to CFH1 and placed as close as possible to the device.
B2, B5	PMID	P	Connected to the drain of the reverse blocking NFET. One 10μF capacitor must be connected from PMID to GND and placed as close as possible to the device.
B3	DP_ SYNCOUT	AIO	Positive line of the USB data line pair. DP/DM based USB host/charging port detection. In the parallel configuration, connect this pin to BATN/SRP_SYNCIN pin of the slave.
B4	DM_TS	AIO	Negative line of the USB data line pair. DP/DM based USB host/charging port detection. This pin has another function as a temperature sensing input. Requires external NTC thermistor, resistor divider and voltage reference.
B6	BST2	P	The high-side MOSFET driver positive supply. One 0.1μF capacitor must be connected from BST2 to CFH2 and placed as close as possible to the device.
C1, C2	CFH1	P	Flying capacitor positive node. Three 22μF capacitors must be connected from CFL1 to CFH1 and placed as close as possible to the device. These pins must be connected together on the PCB.
C3	SDA	DIO	I^2C serial data line. Connect to pull-up voltage via 10kΩ pull-up resistor.
C4	SCL	DI	I^2C serial clock line. Connect to pull-up voltage via 10kΩ pull-up resistor.
C5, C6	CFH2	P	Flying capacitor positive node. Three 22μF capacitors must be connected from CFL2 to CFH2 and placed as close as possible to the device. These pins must be connected together on the PCB.
D1, D2, D5, D6	VOUT	P	Power supply. Connect to positive terminal of the battery pack. These pins must be connected together on the PCB. Two 10μF capacitors must be connected from VOUT to GND and placed as close as possible to the device.
D3	BATN/SRP_ SYNCIN	AI	Negative input for battery voltage sensing and positive input for battery current sensing. Place a 5mΩ or 2mΩ resistor between BATN/SRP_SYNCIN and SRN_ADDR. Connect a 100Ω resistor in series with negative terminal of battery pack if battery current sensing is not used. In parallel configuration, connect this pin to DP_SYNCOUT pin of master.

Pin No.	Pin Name	I/O	Pin Function
D4	SRN_ADDR	AI	Negative input for battery current sensing. Place 5mΩ or 2mΩ resistor between SRN_ADDR and BATN/SRP_SYNCIN. Connect SRN_ADDR to GND to set slave address = 0x6F, or float SRN_ADDR to set slave address = 0x6E. To set slave address = 0x6E, the parasitic capacitance of the SRN_ADDR pin must be less than 100pF.
E1, E2	CFL1	P	Flying capacitor negative node. Three 22μF capacitors must be connected from CFL1 to CFH1 and placed as close as possible to the device. These pins must be connected together on the PCB.
E3	BATP	AI	Positive input for battery voltage sensing. Connect a 100Ω resistor in series with positive terminal of battery pack.
E4	$\overline{INT}$	DO	Open drain interrupt output. Connect to pull-up voltage via 10kΩ pull-up resistor. Normally high, when event happen, $\overline{INT}$ pin sends a 256μs low pulse to the system.
E5, E6	CFL2	P	Flying capacitor negative node. Three 22μF capacitors must be connected from CFL2 to CFH2 and placed as close as possible to the device. These pins must be connected together on the PCB.
F1, F2, F5, F6	GND	P	Power ground.
F3	AGND	AI	Analog ground.
F4	REGN	AO	Internal LDO output. This pin is the internal power supply VDDA. One 4.7μF capacitor must be connected from REGN to AGND and placed as close as possible to the device. Do not use this pin for other function.

Functional Block Diagram



Absolute Maximum Ratings (Note 1)

- Supply Pin Voltage, VAC ---------- –0.3V to 37V
- Supply Pin Voltage, VBUS ---------- –0.3V to 22V
- Supply Pin Voltage, VOUT ---------- –0.3V to 6V
- Control Pin Voltage, OVPGATE (Note 2) ---------- –0.3V to 37V
- Terminal Pin Voltage, OVPGATE to VBUS ---------- –22V to 14V
- Terminal Pin Voltage, PMID ---------- –0.3V to 14V
- Terminal Pin Voltage, DP_SYNCOUT, DM_TS ---------- –0.3V to 6V
- Terminal Pin Voltage, BST1, BST2 ---------- –0.3V to 18V
- Terminal Pin Voltage, BST1 to CFH1, BST2 to CFH2 ---------- –0.3V to 14V
- Terminal Pin Voltage, CFH1, CFH2 ---------- –0.3V to 12V
- Terminal Pin Voltage, CFL1, CFL2 ---------- –0.3V to 6V
- Terminal Pin Voltage, PMID to CFH1, PMID to CFH2 ---------- –0.3V to 6V
- Terminal Pin Voltage, CFH1 to VOUT, CFH2 to VOUT ---------- –0.3V to 6V
- Terminal Pin Voltage, CFH1 to CFL1, CFH2 to CFL2 ---------- –0.3V to 6V
- Terminal Pin Voltage, VOUT to CFL1, VOUT to CFL2 ---------- –0.3V to 6V
- Terminal Pin Voltage, $\overline{INT}$, SDA, SCL, REGN ---------- –0.3V to 6V
- Terminal Pin Voltage, BATP, BATN/SRP_SYNCIN ---------- –0.3V to 6V
- Terminal Pin Voltage, SRN_ADDR ---------- –0.3V to 6V
- Terminal Pin Voltage, BATN/SRP_SYNCIN to SRN_ADDR ---------- –0.5V to 0.5V
- Terminal Pin Voltage, GND to AGND ---------- –0.5V to 0.5V
- Terminal Pin Current, $\overline{INT}$ ---------- 0mA to 6mA
- Power Dissipation, P_D @ T_A = 25°C

  WL-CSP-36B 2.8x2.8 (BSC) ---------- 3.42W
- Package Thermal Resistance (Note 3)

  WL-CSP-36B 2.8x2.8 (BSC), θ_{JA} ---------- 29.26°C/W
- Lead Temperature (Soldering, 10 sec.) ---------- 260°C
- Junction Temperature ---------- –40°C to 150°C
- Storage Temperature Range ---------- –65°C to 150°C
- ESD Susceptibility (Note 4)

  HBM (Human Body Model), per ANSI/ESDA/JEDEC JS-001 ---------- ±2kV

  CDM (Charged Device Model), per JEDEC Specification JESD22-C101 ---------- ±500V

  Latch-Up ---------- ±100mA

Recommended Operating Conditions (Note 5)

- Supply Pin Voltage Range, VAC ---------- 3V to 17V
- Supply Pin Voltage Range (Device in Operating Mode), VAC ---------- 3V to 12V
- Supply Input Voltage Range (Device in DIV2 Mode), VBUS, ---------- 6V to 11V
- Supply Input Voltage Range (Device in Bypass Mode), VBUS ---------- 3V to 5V
- Output Voltage Range, VOUT---------- 3V to 5V
- Positive Flying Capacitor Voltage Range, CFH1, CFH2---------- 0V to 11V
- Negative Flying Capacitor Voltage Range, CFL1, CFL2 ---------- 0V to 5V
- Voltage Range Across Q11 and Q21, PMID to CFH1, PMID to CFH2---------- 0V to 5V
- Voltage Range Across Q12 and Q22, CFH1 to VOUT, CFH2 to VOUT ---------- 0V to 5V
- Voltage Range Across Q13 and Q23, VOUT to CFL1, VOUT to CFL2---------- 0V to 5V
- Analog Sense Voltage Range, BATP ---------- 0V to 5V
- Analog Sense Voltage Range, BATN/SRP_SYNCIN, SRN_ADDR ---------- 0V to 0.04V
- Battery Positive and Negative Voltage Sense Range, BATP to BATN/SRP_SYNCIN---------- 0V to 5V
- I/O Control Voltage Range, SDA, SCL, $\overline{INT}$---------- 0V to 5V
- I/O Control Voltage Range, DP_SYNCOUT, DM_TS ---------- 0V to 3.3V
- Input Current Range (Device in DIV2 Mode), IBUS---------- 0A to 4A
- Input Current Range (Device in Bypass Mode), IBUS ---------- 0A to 5A
- Ambient Temperature Range ---------- –40°C to 85°C
- Junction Temperature Range ---------- –40°C to 125°C

Electrical Characteristics

(T_A = 25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
External OVP Control						
OVPGATE Voltage	$V_{OVPGATE}$	Operation voltage $V_{OVPGATE}$ – V_{BUS}. V_{AC} = 3V to 3.5V or V_{BUS} = 3V to 3.5V. Set by Register 0x0004[0] = 1.	7	10	11	V
		Operation voltage $V_{OVPGATE}$ – V_{BUS}. V_{AC} = 3.5V to 9V or V_{BUS} = 3.5V to 9V. Set by Register 0x0004[0] = 1.	9	10	11	
		Operation voltage $V_{OVPGATE}$ – V_{BUS}. V_{AC} = 3V to 9V or V_{BUS} = 3V to 9V. Set by Register 0x0004[0] = 0.	4.5	4.8	5.1	
VAC Insert Threshold	$V_{AC\_INSERT\_TH}$	V_{AC} rising threshold to turn on external MOS	2.6	2.8	3	V
VAC Insert Threshold Rising Deglitch Time	$t_{VAC\_INSERT\_RIS\_DEG}$	Deglitch between V_{AC} over $V_{AC\_INSERT\_TH}$ and sent an $\overline{INT}$.	--	1	--	ms

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
VAC Insert Hysteresis	$V_{AC\_INSERT\_HY}$	V_{AC} falling hysteresis to turn off external MOS	250	500	750	mV
VBUS Insert Threshold	$V_{BUS\_INSERT\_TH}$	V_{BUS} rising threshold to turn on external MOS	2.65	2.8	2.95	V
VBUS Insert Threshold Rising Deglitch Time	$t_{BUS\_INSERT\_RIS\_DEG}$		--	17	--	μs
VBUS Insert Hysteresis	$V_{BUS\_INSERT\_HY}$	V_{BUS} falling hysteresis to turn off external MOS	50	150	250	mV
VAC Insert Deglitch Time	$t_{VAC\_INSERT\_DEG}$	V_{OUT} < $V_{OUT\_INSERT\_TH}$. Deglitch time between V_{AC} higher than $V_{AC\_INSERT\_TH}$ and start to turn on external MOS. (Note 6)	22	25	28	ms
		V_{OUT} > $V_{OUT\_INSERT\_TH}$. Deglitch time between V_{AC} higher than $V_{AC\_INSERT\_TH}$ and start to turn on external MOS. (Note 6)	20	22	24	
VAC OVP Range	$V_{AC\_OVP\_RAN}$	I^2C programmable, 3-bit DAC, 6.5V, 11V to 17V (Note 7)	6.5	--	17	V
VAC OVP Accuracy	$V_{AC\_OVP\_ACC}$	V_{AC_OVP} threshold accuracy	–2	--	2	%
VAC OVP Hysteresis	$V_{AC\_OVP\_HY}$	V_{AC} falling to turn on external MOS after VAC OVP happen.	250	500	750	mV
OVPGATE Reaction Time	$t_{VAC\_OVP\_RE}$	Duration between V_{AC} over V_{AC_OVP} threshold and OVPGATE start to turn off external MOS. V_{AC_OVP} set 17V, V_{AC} slew rate = 12V/μs, V_{AC} rises from 5V to 22V. (Note 6)	--	100	--	ns
OVPGATE Turn-Off Time	$t_{VAC\_OVP\_OFF}$	Duration between OVPGATE start to turn off external MOS and the external MOS be fully turn off, C_{GS} = 4nF. (Note 6)	--	100	--	ns
Regulation Time Out	$t_{REG\_TIMEOUT}$	If device in regulation and no VDR_OVP for this time, the device will stop charge.	585	650	715	ms
Power Select and Source						
VBUS Quiescent Current	I_{BUS_IQ}	ADC disable, charge disable, OVPGATE disable, VBUS and VAC are open, VOUT no present, no VBUS_OVP happen. Measure quiescent current on VBUS. V_{BUS} = 3V to 12V.	--	250	300	μA

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
VAC Quiescent Current	I_{AC_IQ}	ADC disable, charge disable, OVPGATE disable, VOUT no present. Measure quiescent current on VAC. V_{AC} = 12V, V_{BUS} = 0V.	--	250	300	μA
		ADC disable, charge disable, OVPGATE enable, VOUT no present, no VAC_OVP happen. Measure quiescent current on VAC. V_{AC} = 0V to 12V.	--	650	--	μA
		ADC enable, charge disable, OVPGATE enable, VOUT no present. Measure quiescent current on VAC. V_{AC} = 3V to 12V.	--	3	4	mA
VOUT Quiescent Current	I_{OUT_IQ}	ADC disable, charge disable. VAC no present. EN_I2C_ LEVEL_DETECTION = 0, V_{OUT} falling from 4.5V to 0V. Measure quiescent current on VOUT.	--	5	10	μA
		ADC enable, charge disable. VAC no present. Measure quiescent current on VOUT. V_{OUT} = 0V to 4.5V.	--	2	3	mA
VDDA UVLO Threshold	$V_{DDA\_UVLO\_TH}$	V_{DDA} rising	2.45	2.6	2.75	V
VDDA UVLO Hysteresis	$V_{DDA\_UVLO\_HY}$	V_{DDA} falling to turn off REGN and stop ADC function.	100	250	400	mV
VDDA UVLO Falling Threshold	$V_{DDA\_UVLO\_F}$	V_{DDA} falling to stop I^2C work.	--	2	--	V
Device Wake Up Time	t_{WAKE_UP}	Duration time between V_{DDA} > $V_{DDA\_UVLO\_TH}$ and device can start I^2C communicate.	--	--	2.5	ms
Soft-Start Time	t_{SOFT_START}	Duration time between CHG_EN = 1 and the device start switching	--	--	92	ms
VOUT Insert Threshold	$V_{OUT\_INSERT\_TH}$	V_{OUT} rising	2.65	2.8	2.95	V
VOUT Insert Threshold Rising Deglitch Time	$t_{VOUT\_INSERT\_RIS\_DEG}$		--	17	--	μs
VOUT Insert Hysteresis	$V_{OUT\_INSERT\_HY}$	V_{OUT} falling	50	150	250	mV

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Cap Divider Charger						
Q0 RON	R_{Q0}	DIV2 mode, charge enable. V_{BUS} = 9V, V_{OUT} = 4.5V.	--	7.1	11	mΩ
Q11, Q21 RON	R_{Q11}, R_{Q21}	DIV2 mode, charge enable. V_{BUS} = 9V, V_{OUT} = 4.5V.	--	12	19	mΩ
Q12, Q22 RON	R_{Q12}, R_{Q22}	DIV2 mode, charge enable. V_{BUS} = 9V, V_{OUT} = 4.5V.	--	9.5	13	mΩ
Q13, Q23 RON	R_{Q13}, R_{Q23}	DIV2 mode, charge enable. V_{BUS} = 9V, V_{OUT} = 4.5V.	--	12.5	19.5	mΩ
Q14, Q24 RON	R_{Q14}, R_{Q24}	DIV2 mode, charge enable. V_{BUS} = 9V, V_{OUT} = 4.5V.	--	11	17	mΩ
Bypass Mode RON (VBUS to VOUT)	R_{BYPASS_MODE}	Bypass mode, charge enable. V_{OUT} = 4.5V.	--	17.85	27	mΩ
Charge Switch Frequency Range	f_{SW}		100	--	1000	kHz
Charge Switch Frequency Step Size	f_{SW_SIZE}		--	100	--	kHz
Charge Switch Frequency Accuracy	f_{SW_ACC}	f_{SW} = 200kHz to 1000kHz	–10	--	10	%
Protection						
VBAT OVP Range	$V_{BAT\_OVP\_RAN}$	Rising	4.2	--	4.975	V
VBAT OVP Step Size	$V_{BAT\_OVP\_SIZE}$		--	25	--	mV
VBAT OVP Accuracy	$V_{BAT\_OVP\_ACC}$	V_{BAT_OVP} = 4.4V to 4.55V	–1	--	1	%
		V_{BAT_OVP} = 4.2V to 4.65V	–1.5	--	1.5	
VBAT OVP Deglitch Time	$t_{VBAT\_OVP\_DEG}$		--	3	--	μs
BATP Leakage Current	I_{LKG_BATP}		--	--	1.2	μA
BATN Leakage Current	I_{LKG_BATN}		--	--	1	μA
IBAT_OCP Range	$I_{BAT\_OCP\_RAN}$	Rising	2	--	8.3	A
IBAT_OCP Step Size	$I_{BAT\_OCP\_SIZE}$		--	100	--	mA
IBAT_OCP Accuracy	$I_{BAT\_OCP\_ACC}$	I_{BAT_OCP} = 3A to 8A, R_{SEN} = 0.002Ω	–200	--	200	mA
IBAT OCP Deglitch Time	$t_{IBAT\_OCP\_DEG}$		--	50	--	μs
VBUS OVP Range	$V_{BUS\_OVP\_RAN}$	DIV2 mode. V_{BUS} rising.	6	--	12.3	V
		Bypass mode. V_{BUS} rising.	3	--	6.15	
VBUS OVP Step Size	$V_{BUS\_OVP\_SIZE}$	DIV2 mode	--	100	--	mV
		Bypass mode		50		
VBUS OVP Accuracy	$V_{BUS\_OVP\_ACC}$	DIV2 mode, V_{BUS_OVP} = 8.9V to 11.5V	–1	--	1	%
		Bypass mode, V_{BUS_OVP} = 4.2V to 5V	–1	--	1	
VBUS OVP Hysteresis	$V_{BUS\_OVP\_HY}$	DIV2 mode. V_{BUS} falling.	--	500	--	mV
		Bypass mode. V_{BUS} falling.	--	200	--	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
VBUS OVP Rising Reaction Time	$t_{VBUS\_OVP\_RISE\_RE}$	V_{BUS} rising slope with 10V/μs. ADC enable. During between V_{BUS} over V_{BUS_OVP} threshold and device start to turn off charger and reverse the body diode of Q0. (Note 6)	--	0.1	--	μs
VBUS OVP Falling Reaction Time	$t_{VBUS\_OVP\_FALL\_RE}$	V_{BUS} rising slope with −10V/μs. ADC enable. During between V_{BUS} under $V_{BUS\_OVP\_HY}$ threshold and the body diode of Q0 start to be turned forward. (Note 6)	--	0.1	--	μs
IBUS_OCP Range	$I_{BUS\_OCP\_RAN}$	Rising	1	--	5.5	A
IBUS_OCP Step Size	$I_{BUS\_OCP\_SIZE}$		--	250	--	mA
IBUS_OCP Accuracy	$I_{BUS\_OCP\_ACC}$		−100	--	100	mA
IBUS_OCP Deglitch	$t_{IBUS\_OCP\_DEG}$		--	50	--	μs
IBUS_OCP_H Threshold	$I_{BUS\_OCP\_H}$	Rising (Note 6)	--	6.8	--	A
IBUS_OCP_H Reaction Time	$t_{IBUS\_OCP\_H\_RE}$	During between IBUS over IBUS_OVP_H threshold and device start to turn off charger. (Note 6)	--	2	--	μs
IBUS_UCP_RISE Accuracy	$I_{BUS\_UCP\_RISE\_ACC}$	Rising, IBUS_UCP_RISE = 300mA, set by Register 0x0007[6] = 0	160	300	420	mA
		Rising, IBUS_UCP_RISE = 500mA, set by Register 0x0007[6] = 1	400	500	600	
IBUS_UCP_RISE Deglitch Time	$t_{IBUS\_UCP\_RISE\_DEG}$		--	22	--	μs
IBUS_UCP_FALL Accuracy	$I_{BUS\_UCP\_FALL\_ACC}$	Falling, $I_{BUS\_UCP\_FALL}$ = 150mA, set by Register 0x0007[6] = 0	40	150	320	mA
		Falling, $I_{BUS\_UCP\_FALL}$ = 250mA, set by Register 0x0007[6] = 1	140	250	420	
IBUS_UCP_FALL Deglitch Time	$t_{IBUS\_UCP\_FALL\_DEG}$	$t_{IBUS\_UCP\_FALL\_DEG}$ = 22μs, set by Register 0x005D[3] = 0	--	22	--	μs
		$t_{IBUS\_UCP\_FALL\_DEG}$ = 5ms, set by Register 0x005D[3] = 1	--	5	--	ms

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
IBUS UCP Time Out	$t_{IBUS\_UCP\_TIMEOUT}$	$t_{BUS\_UCP\_TIMEOUT}$ = 12.5ms, set by Register 0x005D[7:5] = 001	11.25	12.5	13.75	ms
		$t_{BUS\_UCP\_TIMEOUT}$ = 25ms, set by Register 0x005D [7:5] = 010	22.5	25	27.5	
		$t_{BUS\_UCP\_TIMEOUT}$ = 50ms, set by Register 0x005D [7:5] = 011	45	50	55	
		$t_{BUS\_UCP\_TIMEOUT}$ = 100ms, set by Register 0x005D [7:5] = 100	90	100	110	
		$t_{BUS\_UCP\_TIMEOUT}$ = 400ms, set by Register 0x005D [7:5] = 101	360	400	440	
		$t_{BUS\_UCP\_TIMEOUT}$ = 1.5s, set by Register 0x005D [7:5] = 110	1.35	1.5	1.65	sec
		$t_{BUS\_UCP\_TIMEOUT}$ = 100s, set by Register 0x005D [7:5] = 111	90	100	110	
VDR OVP Accuracy	$V_{DR\_OVP\_ACC}$	Rising, VDR_OVP = 300mV	200	300	400	mV
VDR OVP Deglitch Time	$t_{VDR\_OVP\_DEG}$	$t_{VDR\_OVP\_DEG}$ = 8µs, set by Register 0x0005[4] = 0	--	8	--	µs
		$t_{VDR\_OVP\_DEG}$ = 5ms, set by Register 0x0005[4] = 1	--	5	--	ms
VOUT OVP Accuracy	$V_{OUT\_OVP\_ACC}$	Rising, V_{OUT_OVP} = 4.9V	4.8	4.9	5	V
VOUT OVP Deglitch Time	$t_{VOUT\_OVP\_DEG}$		--	3	--	µs
Thermal Shutdown Threshold	$T_{DIE\_OTP\_TH}$	Rising	130	140	150	°C
Thermal Shutdown Hysteresis	$T_{DIE\_OTP\_HY}$	Falling	--	20	--	°C
Thermal Shut Down Deglitch Time	t_{TDIE_DEG}		--	3	--	µs
VBUS_HIGH_ERR Accuracy	$V_{BUS\_HIGH\_ERR\_ACC}$	DIV2 mode. V_{BUS} rising. $V_{BUS\_HIGH\_ERR}$ = V_{BUS}/V_{OUT}	2.328	2.4	2.472	V/V
		Bypass mode. V_{BUS} rising. $V_{BUS\_HIGH\_ERR}$ = V_{BUS}/V_{OUT}	1.14	1.2	1.26	
VBUS_LOW_ERR Accuracy	$V_{BUS\_LOW\_ERR\_ACC}$	DIV2 mode. V_{BUS} falling. $V_{BUS\_LOW\_ERR}$ = V_{BUS}/V_{OUT}	2	2.04	2.08	V/V
		Bypass mode. V_{BUS} falling. $V_{BUS\_LOW\_ERR}$ = V_{BUS}/V_{OUT}	0.905	0.952	1	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
CFLY Short Detect Level	R_{CFLY_DIAG}	In V_{BAT} = 4V, if device detect the short resistance of flying capacitor smaller than this level while soft-start duration, the device will stop charging.	--	--	16	Ω
Alarm						
VBAT_OVP_ALM Range	$V_{BAT\_OVP\_ALM\_RAN}$	Rising	4.2	--	4.975	V
VBAT_OVP_ALM Step Size	$V_{BAT\_OVP\_ALM\_SIZE}$		--	25	--	mV
VBAT_OVP_ALM Hysteresis	$V_{BAT\_OVP\_ALM\_HY}$	Falling	--	50	--	mV
VBAT_OVP_ALM Accuracy	$V_{BAT\_OVP\_ALM\_ACC}$	$V_{BAT\_OVP\_ALM}$ = 4.2V to 4.5V	–0.5	--	0.5	%
IBAT_OCP_ALM Range	$I_{BAT\_OCP\_ALM\_RAN}$	Rising	2	--	8.3	A
IBAT_OCP_ALM Step Size	$I_{BAT\_OCP\_ALM\_SIZE}$		--	100	--	mA
IBAT_OCP_ALM Hysteresis	$I_{BAT\_OCP\_ALM\_HY}$	Falling	--	100	--	mA
IBAT_OCP_ALM Accuracy	$I_{BAT\_OCP\_ALM\_ACC}$	$I_{BAT\_OCP\_ALM}$ = 3A to 6A, R_{SEN} = 0.002Ω	–200	--	200	mA
IBAT_UCP_ALM Range	$I_{BAT\_UCP\_ALM\_RAN}$	Falling	0	--	3.15	A
IBAT_UCP_ALM Step Size	$I_{BAT\_UCP\_ALM\_SIZE}$		--	50	--	mA
IBAT_UCP_ALM Hysteresis	$I_{BAT\_UCP\_ALM\_HY}$	Rising	--	50	--	mA
IBAT_UCP_ALM Accuracy	$I_{BAT\_UCP\_ALM\_ACC}$	$I_{BAT\_UCP\_ALM}$ = 3A, R_{SEN} = 0.002Ω	–200	--	200	mA
VBUS_OVP_ALM Range	$V_{BUS\_OVP\_ALM\_RAN}$	DIV2 mode. V_{BUS} rising.	6	--	12.3	V
		Bypass mode. V_{BUS} rising.	3	--	6.15	
VBUS_OVP_ALM Step Size	$V_{BUS\_OVP\_ALM\_SIZE}$	DIV2 mode	--	100	--	mV
		Bypass mode	--	50	--	
VBUS_OVP_ALM Hysteresis	$V_{BUS\_OVP\_ALM\_HY}$	DIV2 mode. V_{BUS} falling.	--	100	--	mV
		Bypass mode. V_{BUS} falling.	--	50	--	
VBUS_OVP_ALM Accuracy	$V_{BUS\_OVP\_ALM\_ACC}$	Falling, $V_{BUS\_OVP\_ALM}$ = 6V to 9V.	–35	--	35	mV
IBUS_OCP_ALM Range	$I_{BUS\_OCP\_ALM\_RAN}$	Rising	0	--	6	A
IBUS_OCP_ALM Step Size	$I_{BUS\_OCP\_ALM\_SIZE}$		--	100	--	mA
IBUS_OCP_ALM Hysteresis	$I_{BUS\_OCP\_ALM\_HY}$	Falling	--	100	--	mA
IBUS_OCP_ALM Accuracy	$I_{BUS\_OCP\_ALM\_ACC}$	$I_{BUS\_OCP\_ALM}$ = 1A to 4A	–150	--	150	mA
IBUS_UCP_ALM Range	$I_{BUS\_UCP\_ALM\_RAN}$	Rising	0	--	3.175	A

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
IBUS_UCP_ALM Step Size	$I_{BUS\_UCP\_ALM\_SIZE}$		--	25	--	mA
IBUS_UCP_ALM Hysteresis	$I_{BUS\_UCP\_ALM\_HY}$	Falling	--	50	--	mA
IBUS_UCP_ALM Accuracy	$I_{BUS\_UCP\_ALM\_ACC}$	$I_{BUS\_UCP\_ALM}$ = 0.3A to 0.5A	–150	--	150	mA
TDIE_OTP_ALM Range	$T_{DIE\_OTP\_ALM\_RAN}$	Rising	25	--	152.5	°C
TDIE_OTP_ALM Step Size	$T_{DIE\_OTP\_ALM\_SIZE}$		--	1	--	°C
TDIE_OTP_ALM Hysteresis	$T_{DIE\_OTP\_ALM\_HY}$	Falling	--	10	--	°C
TDIE_OTP_ALM Accuracy	$T_{DIE\_OTP\_ALM\_ACC}$		–4	--	4	°C
DP_OV_ALM Rising Threshold	$V_{DP\_OV\_ALM\_TH}$	Rising	--	4.5	--	V
DP_OV_ALM Hysteresis	$V_{DP\_OV\_ALM\_HY}$	Falling	--	100	--	mV
DP_OV_ALM Accuracy	$V_{DP\_OV\_ALM\_ACC}$		–50	--	50	mV
DM_OV_ALM Rising Threshold	$V_{DM\_OV\_ALM\_TH}$	Rising	--	4.5	--	V
DM_OV_ALM Hysteresis	$V_{DM\_OV\_ALM\_HY}$	Falling	--	100	--	mV
DM_OV_ALM Accuracy	$V_{DM\_OV\_ALM\_ACC}$		–50	--	50	mV
ADC Specification						
ADC Sample Rate	f_{SAMPLE_RATE}		1800	2000	2200	kHz
ADC Data Rate	t_{DATA_ADC}	12bit, 128 averages Report data for each channel	--	1.2	--	ms
VBUS ADC Range	$V_{BUS\_ADC\_RAN}$		0	--	14	V
VBUS ADC Accuracy	$V_{BUS\_ADC\_ACC}$	V_{BUS} = 6V to 9V	–35	--	35	mV
		V_{BUS} = 3.3V to 11.5V	–2	--	2	%
IBUS ADC Range	$I_{BUS\_ADC\_RAN}$		0	--	6	A
IBUS ADC Accuracy	$I_{BUS\_ADC\_ACC}$	I_{BUS} = 2A	–5	--	5	%
		I_{BUS} = 0A to 4A	–150	--	150	mA
VOUT ADC Range	$V_{OUT\_ADC\_RAN}$		0	--	5	V
VOUT ADC Accuracy	$V_{OUT\_ADC\_ACC}$	V_{OUT} = 3V to 4.5V	–20	--	20	mV
VBAT ADC Range	$V_{BAT\_ADC\_RAN}$		0	--	5	V
VBAT ADC Accuracy	$V_{BAT\_ADC\_ACC}$	V_{BAT} = 3V to 4.5V	–0.5	--	0.5	%
		V_{BAT} = 4.45V	–10	--	10	mV
IBAT ADC Range	$I_{BAT\_ADC\_RAN}$		0	--	10	A

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
IBAT ADC Accuracy	$I_{BAT\_ADC\_ACC}$	I_{BAT} = 3A to 8A, R_{SEN} = 0.002Ω	–200	--	200	mA
		I_{BAT} = 2A, R_{SEN} = 0.002Ω	–5	--	5	%
		I_{BAT} = 7A, R_{SEN} = 0.002Ω	–2	--	2	
TDIE ADC Range	$T_{DIE\_ADC\_RAN}$		–40	--	152.5	°C
TDIE ADC Accuracy	$T_{DIE\_ADC\_ACC}$	T_J = 25°C	–4	--	4	°C
DP_ADC Range	$D_{P\_ADC\_RAN}$		0	--	5	V
DP_ADC Accuracy	$D_{P\_ADC\_ACC}$		–50	--	50	mV
DM_ADC Range	$D_{M\_ADC\_RAN}$		0	--	5	V
DM_ADC Accuracy	$D_{M\_ADC\_ACC}$		–50	--	50	mV
REGN						
REGN LDO Output Voltage	V_{REGN}	ADC enabled, $V_{BUS} \geq$ 5.5V	4.9	5	5.1	V
		ADC enabled, V_{BUS} < 5.5V, Without VAC and VOUT, $V_{BUS} > V_{DDA\_UVLO\_TH}$	V_{BUS} - 0.7	V_{BUS}	V_{BUS} + 0.1	
		Without VAC and VOUT, $V_{OUT} > V_{DDA\_UVLO\_TH}$	V_{OUT} - 0.1	V_{OUT}	V_{OUT} + 0.1	
Pull-Down						
VAC Pull-Down Resistor	R_{VAC_PD}	V_{AC} < 5V	--	270	--	Ω
		V_{AC} > 5V	--	22	--	mA
VAC Pull-Down Time Out	t_{VAC_PD}		360	400	440	ms
VBUS Pull-Down Resistor	R_{VBUS_PD}	V_{BUS} = 3V to 14V	0.6	1	1.4	kΩ

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Watchdog Time Out						
Watchdog Time Out	WDT	No I²C communication for 0.5s, set by Register 0x0000[2:0] = 000 (Note 6)	0.45	0.5	0.55	sec
		No I²C communication for 1s, set by Register 0x0000[2:0] = 001 (Note 6)	0.9	1	1.1	
		No I²C communication for 5s, set by Register 0x0000[2:0] = 010 (Note 6)	4.5	5	5.5	
		No I²C communication for 30s, set by Register 0x0000[2:0] = 011 (Note 6)	27	30	33	
		No I²C communication for 40s, set by Register 0x0000[2:0] = 100 (Note 6)	36	40	44	
		No I²C communication for 80s, set by Register 0x0000[2:0] = 101 (Note 6)	72	80	88	
		No I²C communication for 128s, set by Register 0x0000[2:0] = 110 (Note 6)	115.2	128	140.8	
		No I²C communication for 255s, set by Register 0x0000[2:0] = 111 (Note 6)	229.5	255	280.5	
Logic Output Pin ($\overline{INT}$)						
$\overline{INT}$ Output Low Threshold	V_{OL_INT}	Sink current = 100μA	--	--	0.1	V
		Sink current = 2mA	--	--	0.3	
$\overline{INT}$ High Level Leakage Current	I_{LKG_INT}	Pull-up rail 1.8V	--	--	1	μA
$\overline{INT}$ Pin Pull-Low Time	$t_{INT\_PULL\_LOW}$		--	256	--	μs
Synchronize Function						
DP_SYNCOUT Output High Threshold	$V_{OH\_DP\_SYNCOUT}$	Register 0x005F[7] = 1	V_{REGN} - 0.4	--	--	V
DP_SYNCOUT Output Low Threshold	$V_{OL\_DP\_SYNCOUT}$	Register 0x005F[7] = 1	--	--	0.2	V
BATN/SRP_SYNCIN Input High Threshold	V_{IH_BATN/SRP_SYNCIN}	Register 0x005F[5] = 1	V_{REGN} x 0.75	--	--	V
BATN/SRP_SYNCIN Input Low Threshold	V_{IL_BATN/SRP_SYNCIN}	Register 0x005F[5] = 1	--	--	V_{REGN} x 0.25	V

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
VDD of I²C Detection						
VDD Level of I²C Detection Threshold	$V_{TH\_I2C\_level}$	VDD level of I²C = 1.2V when SDA voltage < $V_{TH\_I2C\_level}$. VDD level of I²C = 1.8V when SDA voltage > $V_{TH\_I2C\_level}$. (VDD level of I²C can only change to 1.8V from 1.2V. It cannot change to 1.2V from 1.8V.)	1.3	1.5	1.65	V
V_{SDA} Rising Deglitch Time	t_{I2C_level}		--	17.5	--	μs
DP/DM Detection						
DP Source Voltage	V_{DP_SRC}		0.5	0.6	0.7	V
DM Source Voltage	V_{DM_SRC}		0.5	0.6	0.7	V
Data Detect Voltage	V_{DAT_REF}		0.25	0.325	0.4	V
Logic Threshold Voltage	V_{LGC_CHG}		0.8	--	2	V
DP Sink Current	I_{DP_SINK}		25	45	65	μA
DM Sink Current	I_{DM_SINK}		25	45	65	μA
Data Contact Detect Current Source	I_{DP_SRC}		7	10	13	μA
DP Pull-Down Resistance	R_{DP_DWN}		14.25	20	24.8	kΩ
DM Pull-Down Resistance	R_{DM_DWN}		14.25	20	24.8	kΩ
DP Source On-Time	$t_{DP\_SRC\_ON}$		40	64	80	ms
DM Source On-Time	$t_{DM\_SRC\_ON}$		40	64	80	ms
DCD Timeout	$t_{DCD\_TIMEOUT}$	Register 0x0044[6:5] = 01	300	--	900	ms

I²C Characteristics

(Note 6)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
SCL, SDA High-Level Input Threshold Voltage	V_{IH_I2C}	I2C_level = 1.8V	1.17	--	--	V
		I2C_level = 1.2V	0.78	--	--	
SCL, SDA Low-Level Input Threshold Voltage	V_{IL_I2C}	I2C_level = 1.8V	--	--	0.63	V
		I2C_level = 1.2V			0.42	
SDA Low-Level Output Threshold Voltage	V_{OL_I2C}	Sink current = 3mA, pull-up rail 1.8V	--	--	0.36	V
		Sink current = 3mA, pull-up rail 1.2V	--	--	0.24	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
SCL Clock Frequency	f_{CLK}	Standard-mode	--	--	100	kHz
		Fast-mode	--	--	400	
		Fast-mode plus	--	--	1000	
		High-speed mode Cb = 400pF	--	--	1.7	MHz
		High-speed mode Cb = 100pF	--	--	3.4	
Bus Free Time between Stop and Start Condition	t_{BUF}	Standard-mode	4.7	--	--	µs
		Fast-mode	1.3	--	--	
		Fast-mode Plus	0.5	--	--	
(Repeated) Start Hold Time	$t_{HD;STA}$	Standard-mode	4	--	--	µs
		Fast-mode	0.6	--	--	
		Fast-mode plus	0.26	--	--	
		High-speed mode Cb = 400pF	160	--	--	ns
		High-speed mode Cb = 100pF	160	--	--	
(Repeated) Start Setup Time	$t_{SU;STA}$	Standard-mode	4.7	--	--	µs
		Fast-mode	0.6	--	--	
		Fast-mode plus	0.26	--	--	
		High-speed mode Cb = 400 pF	160	--	--	ns
		High-speed mode Cb = 100 pF	160	--	--	
STOP Condition Setup Time	$t_{SU;STO}$	Standard-mode	4	--	--	µs
		Fast-mode	0.6	--	--	
		Fast-mode plus	0.26	--	--	
		High-speed mode Cb = 400pF	160	--	--	ns
		High-speed mode Cb = 100pF	160	--	--	
SDA Data Hold Time	$t_{HD;DAT}$	Standard-mode	0.1	--	--	ns
		Fast-mode	0.1	--	--	
		Fast-mode plus	0.1	--	--	
		High-speed mode Cb = 400pF	0.1	--	150	
		High-speed mode Cb = 100pF	0.1	--	70	
SDA Valid Acknowledge Time	$t_{VD;ACK}$	Standard-mode	--	--	3.45	µs
		Fast-mode	--	--	0.9	
		Fast-mode plus	--	--	0.45	
SDA Setup Time	$t_{SU;DAT}$	Standard-mode	250	--	--	ns
		Fast-mode	100	--	--	
		Fast-mode plus	50	--	--	
		High-speed mode Cb = 400pF	10	--	--	
		High-speed mode Cb = 100pF	10	--	--	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
SCL Clock Low Time	t_{LOW}	Standard-mode	4.7	--	--	µs
		Fast-mode	1.3	--	--	
		Fast-mode Plus	0.5	--	--	
		High-speed mode Cb = 400pF	320	--	--	ns
		High-speed mode Cb = 100pF	160	--	--	
SCL Clock High Time	t_{HIGH}	Standard-mode	4	--	--	µs
		Fast-mode	0.6	--	--	
		Fast-mode Plus	0.26	--	--	
		High-speed mode Cb = 400pF	120	--	--	ns
		High-speed mode Cb = 100pF	60	--	--	

Note 1. Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

Note 2. For testing absolute maximum rating of OVPGATE pin, VBUS pin should be power-on with 20V initially. After VBUS has kept 20V for 25.6ms, the OVPGATE can be biased.

Note 3. θ_{JA} is measured under natural convection (still air) at T_A = 25°C with the component mounted on a high effective-thermal-conductivity four-layer test board on a JEDEC 51-7 thermal measurement standard.

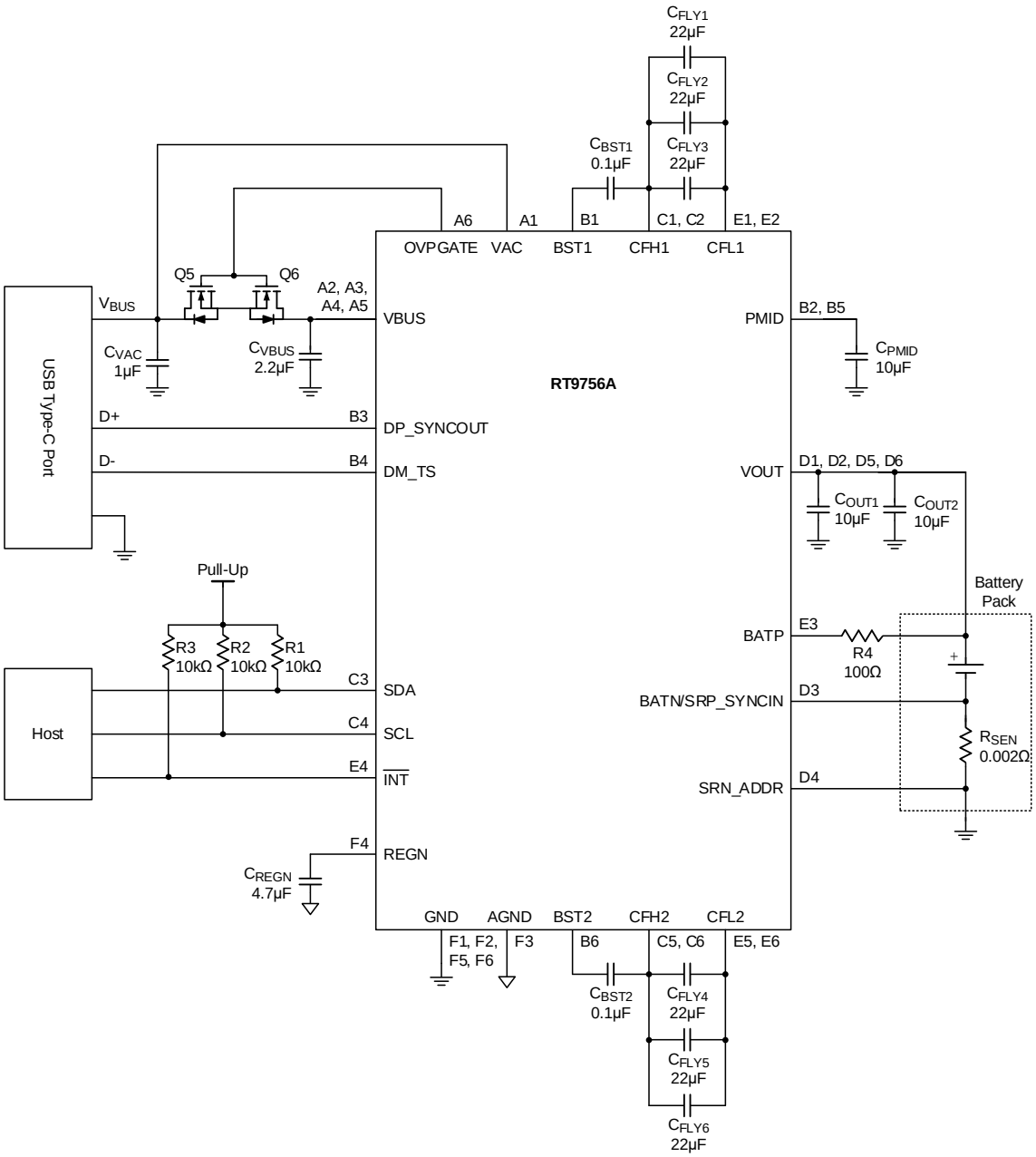
Note 4. Devices are ESD sensitive. Handling precautions are recommended.

Note 5. The device is not guaranteed to function outside its operating conditions.

Note 6. Specification is guaranteed by design and/or correlation with statistical process control.

Note 7. When set Bypass mode, VAC OVP must be 6.5V for surge condition.

Typical Application Circuit

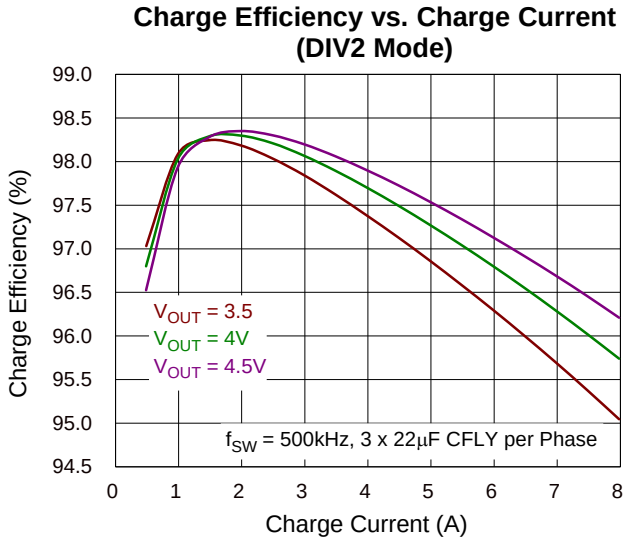


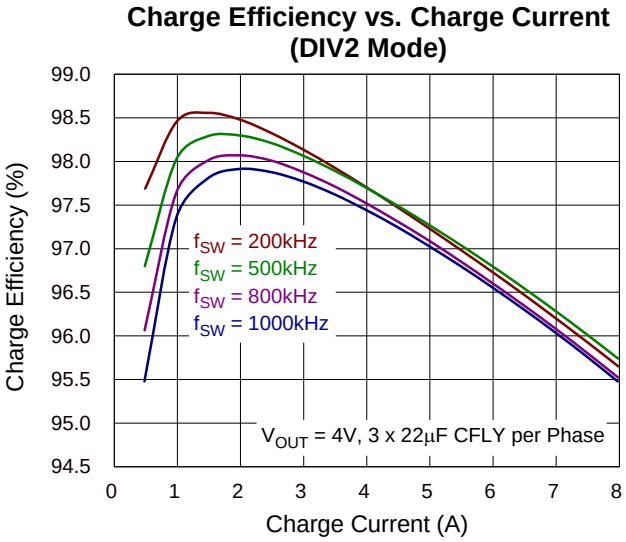
Below are recommended components information

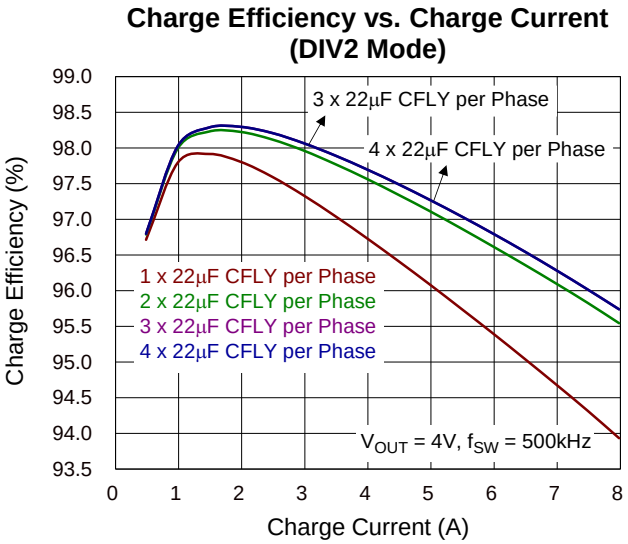
Table 1. BOM List

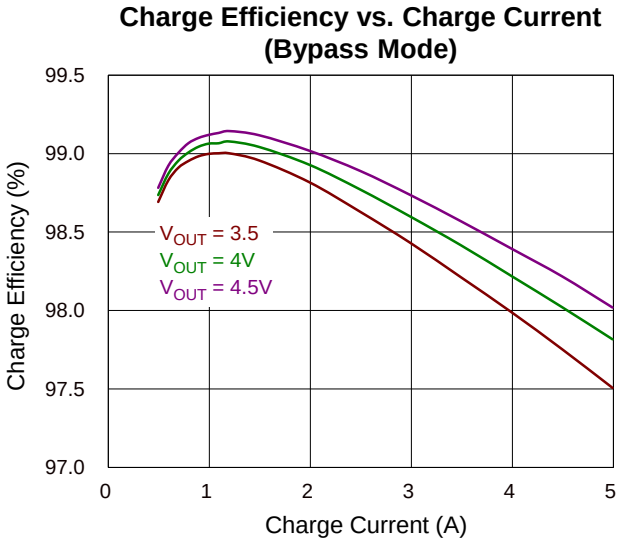
Name	Part Number	Description	Package	Manufacturer
C_{VAC}	GRM155R61H105KE05	CAP, CERM, 1μF, 50V, ±10%, X5R	0402	MuRata
C_{VBUS}	GRM155R61E225KE11	CAP, CERM, 2.2μF, 25V, ±10%, X5R	0402	MuRata
Q5, Q6	PSMN2R4-30MLD	N-Channel 30V, 2.4mΩ logic level MOSFET in LFPAK33, using NextPowerS3 Technology	LFPAK33	Nexperia
C_{FLY1}, C_{FLY2}, C_{FLY3}, C_{FLY4}, C_{FLY5}, C_{FLY6}	GRM187R61A226ME15	CAP, CERM, 22μF, 10V, ±20%, X5R	0603	MuRata
C_{OUT1}, C_{OUT2}	GRM185R60J106ME15	CAP, CERM, 10μF, 6.3V, ±20%, X5R	0603	MuRata
C_{PMID}	GRM188R61E106MA73	CAP, CERM, 10μF, 25V, ±20%, X5R	0603	MuRata
C_{BST1}, C_{BST2}	GRM033R61C104KE14	CAP, CERM, 0.1μF, 16V, ±10%, X5R	0201	MuRata
C_{REGN}	GRM155R61A475MEAAD	CAP, CERM, 4.7μF, 10V, ±20%, X5R	0402	MuRata
R1, R2, R3	WR04X1002FTL	RES, 10k, 1%, 0.0625W	0402	Walsin
R4	CR0402F100RQ10Z	RES, 100Ω, 1%, 0.063W	0402	EVER OHMS
R_{SEN}	CSNL1206FT2L00	RES, 0.002, 1%, 1W	1206	Stackpole Electronics Inc

Typical Operating Characteristics









Register Description

Register Map

Function Name	STAT	FLAG	MASK	Threshold/ Setting	Enable	Deglitch
REG_RST	--	--	--	--	0x0000[7]	--
CHG_EN	--	--	--	--	0x0000[6]	--
OPERATION_MODE	--	--	--	0x0000[5]	--	--
WDT	--	0x000F[5]	0x0010[5]	0x0000[2:0]	0x0000[3]	--
FSW	--	--	--	0x0001[7:4]	--	--
FSW_SHIFT	--	--	--	0x0001[3:2]	--	--
PHASE_DELAY	--	--	--	0x0001[1:0]	--	--
PHASE_ANGLE	--	--	--	0x0002[3:0]	--	--
OVPGATE	--	--	--	0x0004[0]	0x0004[6]	--
CON_SWITCHING	0x005C[7]	--	0x005C[6]	--	--	--
IC_STAT	0x005C[5:4]	--	--	--	--	--
IBAT_RSEN	--	--	--	0x005E[1:0]	--	--
Pin Configuration	--	--	--	0x005F[7:5]	--	--
VAC_PD	--	0x000B[6]	0x000C[6]	--	0x0005[7]	--
VBUS_PD	--	0x000B[5]	0x000C[5]	--	0x0005[6]	--
CFLY_DIAG	--	0x000F[0]	0x0010[0]	--	0x0002[7]	--
TDIE_OTP	0x004C[3]	0x000D[3]	0x000E[3]	--	0x0002[6]	--
VBUS_LOW_ERR	0x004C[2]	0x000D[2]	0x000E[2]	--	0x0002[5]	--
VBUS_HIGH_ERR	0x004C[1]	0x000D[1]	0x000E[1]	--	0x0002[4]	--
VAC_OVP	0x004B[7]	0x000B[7]	0x000C[7]	0x0004[3:1]	0x0004[4]	--
VDR_OVP	0x004B[4]	0x000B[4]	0x000C[4]	--	0x0005[5]	0x0005[4]
VBUS_OVP	0x004B[3]	0x000B[3]	0x000C[3]	0x0006[5:0]	0x0006[7]	--
IBUS_UCP_RISE	--	0x000B[1]	0x000C[1]	0x0007[6]	0x0007[7]	--
IBUS_UCP_FALL	--	0x000B[0]	0x000C[0]	0x0007[6]	0x0007[7]	0x005D[3]
IBUS_OCP	0x004B[2]	0x000B[2]	0x000C[2]	0x0007[4:0]	0x0007[5]	--
IBUS_OCP_H	--	0x0061[0]	0x0061[1]	--	--	--
VBAT_OVP	0x004C[7]	0x000D[7]	0x000E[7]	0x0008[4:0]	0x0008[7]	--
IBAT_OCP	0x004C[6]	0x000D[6]	0x000E[6]	0x0009[5:0]	0x0009[7]	--
VOUT_OVP	0x004E[0]	0x0049[0]	0x004A[0]	--	0x005E[3]	--
IBAT_REG	0x004C[4]	0x000D[4]	0x000E[4]	0x000A[4:3]	0x000A[5]	--
VBAT_REG	0x004C[5]	0x000D[5]	0x000E[5]	0x000A[1:0]	0x000A[2]	--
VAC_INSERT	0x004C[0]	0x000D[0]	0x000E[0]	--	--	--
VBUS_INSERT	0x004D[7]	0x000F[7]	0x0010[7]	--	--	--
VOUT_INSERT	0x004D[6]	0x000F[6]	0x0010[6]	--	--	--
VAC_UVLO	0x004D[4]	0x000F[4]	0x0010[4]	--	--	--

Function Name	STAT	FLAG	MASK	Threshold/ Setting	Enable	Deglitch
VBUS_UVLO	0x004D[3]	0x000F[3]	0x0010[3]	--	--	--
VDDA_UVLO	--	0x0063[1]	0x0063[0]	--	--	--
IBUS_UCP_TIMEOUT	0x004D[2]	0x000F[2]	0x0010[2]	0x005D[7:5]	--	--
TS_OTP	0x005F[1]	0x005F[3]	0x005F[2]	0x0060[7:0]	0x005F[0]	
ADC	0x004D[1]	0x000F[1]	0x0010[1]	0x0011[6]	0x0011[7]	--
VBUS_ADC	0x0012[5:0] 0x0013[7:0]	--	--	--	0x0011[5]	--
IBUS_ADC	0x0014[5:0] 0x0015[7:0]	--	--	--	0x0011[4]	--
VBAT_ADC	0x0016[5:0] 0x0017[7:0]	--	--	--	0x0011[3]	--
IBAT_ADC	0x0018[5:0] 0x0019[7:0]	--	--	--	0x0011[2]	--
TDIE_ADC	0x001A[7:0]	--	--	--	0x0011[1]	--
VOUT_ADC	0x0056[5:0] 0x0057[7:0]	--	--	--	0x0056[7]	
DP_ADC	0x0058[5:0] 0x0059[7:0]	--	--	--	0x0058[7]	
DM_ADC	0x005A[5:0] 0x005B[7:0]	--	--	--	0x005A[7]	
VBAT_OVP_ALM	0x004E[7]	0x0049[7]	0x004A[7]	0x004F[4:0]	0x004F[7]	--
IBAT_OCP_ALM	0x004E[6]	0x0049[6]	0x004A[6]	0x0050[5:0]	0x0050[7]	--
VBUS_OVP_ALM	0x004E[5]	0x0049[5]	0x004A[5]	0x0051[5:0]	0x0051[7]	--
IBUS_OCP_ALM	0x004E[4]	0x0049[4]	0x004A[4]	0x0052[5:0]	0x0052[7]	--
IBAT_UCP_ALM	0x004E[3]	0x0049[3]	0x004A[3]	0x0053[5:0]	0x0053[7]	--
IBUS_UCP_ALM	0x004E[2]	0x0049[2]	0x004A[2]	0x0054[6:0]	0x0054[7]	--
TDIE_OTP_ALM	0x004E[1]	0x0049[1]	0x004A[1]	0x0055[6:0]	0x0055[7]	--
DP_OV_ALM	0x0061[5]	0x0061[7]	0x0061[3]	--	--	--
DM_OV_ALM	0x0061[4]	0x0061[6]	0x0061[2]	--	--	--
BC1.2	0x0046[7:3] 0x0046[1:0]	0x0045[4:0]	0x0047[4:0]	--	0x0044[7:2]	--
DPDM Manual	--	--	--	0x0048 0x0066 0x006D 0x006E	--	--

Register Description

I²C Slave Address: 1101111 (6FH) when SRN_ADDR pin is connected to GND

I²C Slave Address: 1101110 (6EH) when SRN_ADDR pin is floating

R: Read only

RC: Read and clear

RW: Read and write

RWC: Read and write, also automatically clear by particular condition

RWSC: Read and write, also automatically set/clear by particular condition

Register Address: 0x0000, Register Name: CHG_CTL1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	REG_RST	0	N	Y	RW	Register reset 0: No register reset (default) 1: Reset registers
6	CHG_EN	0	Y	Y	RW	Charger control bit 0: Disable charge (default) 1: Enable charge
5	OPERATION_MODE	1	N	N	RW	This bit selects converter operation mode. 0: Bypass mode 1: DIV2 mode (default)
4	Reserved	0	NA	NA	NA	Reserved
3	WDT_DIS	0	N	Y	RW	Disable Watchdog 0: Enable watchdog (default) 1: Disable watchdog
2:0	WDT_TIMER	000	N	Y	RW	Set the watchdog timer. 000: 0.5s (default) 001: 1s 010: 5s 011: 30s 100: 40s 101: 80s 110: 128s 111: 255s

Register Address: 0x0001, Register Name: CHG_CTL2

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:4	FSW_SET	0100	N	Y	RW	Set the switching frequency. 0000 to 1001: 100kHz to 1000kHz in 100kHz steps 1010 to 1111: Reserved 0100: 500kHz (default)
3:2	FREQ_SHIFT	00	N	Y	RW	Adjust switching frequency for EMI. 00: Nominal frequency (default) 01: Nominal frequency + 10% 10: Nominal frequency - 10% 11: Spread spectrum
1:0	PHASE_ DELAY	00	N	Y	RW	Adjust delay time between two phases. It is strongly prohibited during operation. Should be determined before CHG_EN set 1. 00: 0ns (default) 01: 15ns 10: 30ns 11: 45ns

Register Address: 0x0002, Register Name: CHG_CTL3

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	CFLY_DIAG_EN	1	N	Y	RW	Enable CFLY short protection before charge mode is enabled. 0: Disable 1: Enable (default)
6	TDIE_OTP_EN	1	N	Y	RW	Enable TDIE over-temperature protection. 0: Disable 1: Enable (default)
5	VBUS_LOW_ERR_EN	1	N	Y	RW	Enable VBUS voltage too high error protection before charge mode is enabled. 0: Disable 1: Enable (default)
4	VBUS_HIGH_ERR_EN	1	N	Y	RW	Enable VBUS voltage too low error protection before charge mode is enabled. 0: Disable 1: Enable (default)
3:2	PHASE_A_ANGLE	00	N	Y	RW	Select phase A angle in DIV2 mode. It is strongly prohibited during operation. Should be determined before CHG_EN set 1. 00: 0 degree (default) 01: 90 degree 10: 180 degree 11: 270 degree (If the RT9756A operate in single application, the bits are recommended to set 00. If the RT9756A operates in parallel application and enables synchronous function, the bits are recommended to set 00 in Master mode and 01 in Slave mode.)
1:0	PHASE_B_ANGLE	10	N	Y	RW	Select phase B angle in DIV2 mode. It is strongly prohibited during operation. Should be determined before CHG_EN set 1. 00: 0 degree 01: 90 degree 10: 180 degree (default) 11: 270 degree (If the RT9756A operates in single application, the bits are recommended to set 10. If the RT9756A operates in parallel application and enables synchronous function, the bits are recommended to set 10 in Master mode and 11 in Slave mode.)

Register Address: 0x0003, Register Name: DEVICE_INFO

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:4	Device Revision	0000	Y	Y	R	Device revision
3:0	Device ID	0111	Y	Y	R	Device ID 0111: RICHTEK product

Register Address: 0x0004, Register Name: VAC_PROTECTION

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	Reserved	0	NA	NA	NA	Reserved
6	OVPMOS_DIS	0	Y	Y	RW	Disable OVPGATE. 0: Enable OVPGATE (default) 1: Disable OVPGATE
5	Reserved	0	NA	NA	NA	Reserved
4	VAC_OVP_EN	1	Y	Y	RW	Enable VAC overvoltage protection. 0: Disable 1: Enable (default)
3:1	VAC_OVP	001	N	Y	RW	VAC overvoltage threshold 000-110 is determined by V_{AC_OVP} = 11V + VAC_OVP[2:0] x 1V. Writing all 1 to these bits set the V_{AC_OVP} to 6.5V. Default = 12V
0	OVPGATE	0	N	N	RW	Select OVPMOS VGS voltage. It is strongly prohibited when OVPMOS is turned on. Should be determined before OVPMOS is turned on. 0: 4.8V (default) 1: 10V

Register Address: 0x0005, Register Name: PD_VDR_OVP

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VAC_PD_EN	0	N	N	RW	Enable VAC pull-down resistor. 0: Disable (default) 1: Enable (VAC pull-down resistor is only enable for 400ms, and then this bit is reset to default.)
6	VBUS_PD_EN	0	N	Y	RW	Enable VBUS pull-down resistor. 0: Disable (default) 1: Enable
5	VDR_OVP_EN	1	N	Y	RW	Enable Dropout overvoltage protection. 0: Disable 1: Enable (default)
4	VDR_OVP_DEGLITCH_SET	0	N	Y	RW	This is deglitch time after the device reaches the VDR_OVP threshold before the part stops switching. 0: 8μs (default) 1: 5ms
3:0	Reserved	0000	NA	NA	NA	Reserved

Register Address: 0x0006, Register Name: VBUS_OVP

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBUS_OVP_EN	1	Y	Y	RW	Enable VBUS overvoltage protection. 0: Disable 1: Enable (default)
6	Reserved	0	NA	NA	NA	Reserved
5:0	VBUS_OVP	011101	N	Y	RW	VBUS overvoltage threshold. The setting is determined by difference modes. Device in DIV2 mode: V_{BUS_OVP} = 6V + VBUS_OVP[5:0] X 100mV, Default: 8.9V (b011101) Device in BYPASS mode: V_{BUS_OVP} = 3V + VBUS_OVP[5:0] X 50mV, Default: 4.45V (b011101)

Register Address: 0x0007, Register Name: IBUS_OCP_UCP

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	IBUS_UCP_EN	1	N	Y	RW	Enable IBUS undercurrent protection. 0: Disable 1: Enable (default)
6	IBUS_UCP_THRESHOLD	0	N	Y	RW	This bit is set the IBUS_UCP threshold and it can only be changed prior to enabling switching. The system should control the IBUS current rise to IBUS_UCP_RISE within the IBUS_UCP_TIMEOUT. 0: 300mA rising, 150mA falling (default) 1: 500mA rising, 250mA falling
5	IBUS_OCP_EN	1	N	Y	RW	Enable IBUS overcurrent protection. 0: Disable 1: Enable (default)
4:0	IBUS_OCP	01000	N	Y	RW	IBUS overcurrent threshold. I_{BUS_OCP} = 1A + IBUS_OCP[4:0] x 250mA. 10010 to 11111: I_{BUS_OCP} = 5.5A. Default: 3A (b01000)

Register Address: 0x0008, Register Name: VBAT_OVP

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBAT_OVP_EN	1	N	Y	RW	Enable VBAT overvoltage protection. 0: Disable 1: Enable (default)
6:5	Reserved	00	NA	NA	NA	Reserved
4:0	VBAT_OVP	00110	N	Y	RW	VBAT overvoltage threshold. V_{BAT_OVP} = 4.2V + VBAT_OVP[4:0] x 25mV Default: 4.35V (b00110)

Register Address: 0x0009, Register Name: IBAT_OCP

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	IBAT_OCP_EN	1	N	Y	RW	Enable IBAT overcurrent protection. 0: Disable 1: Enable (default)
6	Reserved	0	NA	NA	NA	Reserved
5:0	IBAT_OCP	110100	N	Y	RW	IBAT overcurrent threshold I_{BAT_OCP} = 2A + IBAT_OCP[5:0] x 100mA Default: 7.2A (b110100)

Register Address: 0x000A, Register Name: REG_CTRL

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:6	Reserved	00	NA	NA	NA	Reserved
5	IBAT_REG_EN	0	N	Y	RW	Enable IBAT current regulation. 0: Disable (default) 1: Enable
4:3	IBAT_REG	00	N	Y	RW	These two bits set the threshold below I_{BAT_OCP} where the part starts regulation. 00: 200mA below I_{BAT_OCP} setting (default) 01: 300mA below I_{BAT_OCP} setting 10: 400mA below I_{BAT_OCP} setting 11: 500mA below I_{BAT_OCP} setting (2A is the minimum level of IBAT_REG.)
2	VBAT_REG_EN	0	N	Y	RW	Enable VBAT voltage regulation. 0: Disable (default) 1: Enable
1:0	VBAT_REG	00	N	Y	RW	These two bits set the threshold below V_{BAT_OVP} where the part starts regulation. 00: 50mV below V_{BAT_OVP} setting (default) 01: 100mV below V_{BAT_OVP} setting 10: 150mV below V_{BAT_OVP} setting 11: 200mV below V_{BAT_OVP} setting (4.2V is the minimum level of IBAT_REG.)

Register Address: 0x000B, Register Name: INT_FLAG1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VAC_OVP_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when a VAC_OVP event occurs. 0: No VAC_OVP Fault 1: VAC_OVP Fault has occurred (Clear upon read.)
6	VAC_PD_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when a VAC pull-down event occurs. 0: No VAC pull down 1: VAC pull down has occurred (Clear upon read.)
5	VBUS_PD_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when a VBUS pull-down event occurs. 0: No VBUS pull down 1: VBUS pull down has occurred (Clear upon read.)
4	VDR_OVP_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when a VDR_OVP has occurred. 0: No VDR_OVP Fault 1: VDR_OVP Fault has occurred (Clear upon read.)
3	VBUS_OVP_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{BUS} is over than V_{BUS_OVP} threshold. 0: No VBUS_OVP Fault. 1: VBUS_OVP Fault has occurred. (Clear upon read.)
2	IBUS_OCP_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when I_{BUS} is over than I_{BUS_OCP} threshold. 0: No IBUS_OCP Fault. 1: IBUS_OCP Fault has occurred. (Clear upon read.)
1	IBUS_UCP_RISE_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when I_{BUS} current is over than $I_{BUS\_UCP\_RISE}$ threshold. 0: No IBUS_UCP rising. 1: IBUS_UCP rising has occurred. (Clear upon read.)
0	IBUS_UCP_FALL_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when I_{BUS} current is lower than $I_{BUS\_UCP\_FALL}$ threshold. 0: No IBUS_UCP falling. 1: IBUS_UCP falling has occurred. (Clear upon read.)

Register Address: 0x000C, Register Name: INT_MASK1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VAC_OVP_ MASK	0	N	Y	RW	Masks a VAC_OVP event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
6	VAC_PD_ MASK	0	N	Y	RW	Masks a VAC_PD event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
5	VBUS_PD_ MASK	0	N	Y	RW	Masks a VBUS_PD event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
4	VDR_OVP_ MASK	0	N	Y	RW	Masks a VDR_OVP event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
3	VBUS_OVP_ MASK	0	N	Y	RW	Masks a VBUS_OVP event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
2	IBUS_OCP_ MASK	0	N	Y	RW	Masks a IBUS_OCP event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
1	IBUS_UCP_ RISE_MASK	0	N	Y	RW	Masks a IBUS_UCP rising event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
0	IBUS_UCP_ FALL_MASK	0	N	Y	RW	Masks a IBUS_UCP falling event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask

Register Address: 0x000D, Register Name: INT_FLAG2

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBAT_OVP_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{BAT} is over than V_{BAT_OVP} threshold. 0: No VBAT_OVP Fault. 1: VBAT_OVP Fault has occurred. (Clear upon read.)
6	IBAT_OCP_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when I_{BAT} is over than I_{BAT_OCP} threshold. 0: No IBAT_OCP Fault. 1: IBAT_OCP Fault has occurred. (Clear upon read.)
5	VBAT_REG_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when VBAT_REG has been active. 0: No VBAT_REG. 1: VBAT_REG has occurred. (Clear upon read.)
4	IBAT_REG_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when IBAT_REG has been active. 0: No IBAT_REG. 1: IBAT_REG has occurred. (Clear upon read.)
3	TDIE_OTP_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when die temperature is over than T_{DIE} threshold. 0: No TDIE_OTP Fault. 1: TDIE_OTP Fault has occurred. (Clear upon read.)
2	VBUS_LOW_ERR_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{BUS} voltage is lower than $V_{BUS\_LOW\_ERR}$ threshold. 0: No VBUS_LOW_ERR Fault. 1: VBUS_LOW_ERR Fault has occurred. (Clear upon read.)
1	VBUS_HIGH_ERR_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{BUS} voltage is over than $V_{BUS\_HIGH\_ERR}$ threshold. 0: No VBUS_HIGH_ERR Fault. 1: VBUS_HIGH_ERR Fault has occurred. (Clear upon read.)
0	VAC_INSERT_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{AC} is over than V_{AC_INSERT} threshold. 0: No VAC_INSERT. 1: VAC_INSERT has occurred. (Clear upon read.)

Register Address: 0x000E, Register Name: INT_MASK2

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBAT_OVP_MASK	0	N	Y	RW	Masks a VBAT_OVP event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
6	IBAT_OCP_MASK	0	N	Y	RW	Masks a IBAT_OCP event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
5	VBAT_REG_MASK	0	N	Y	RW	Masks a VBAT_REG event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
4	IBAT_REG_MASK	0	N	Y	RW	Masks a IBAT_REG event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
3	TDIE_OTP_MASK	0	N	Y	RW	Masks a TDIE_OTP event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
2	VBUS_LOW_ERR_MASK	0	N	Y	RW	Masks a VBUS_LOW_ERR event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
1	VBUS_HIGH_ERR_MASK	0	N	Y	RW	Masks a VBUS_HIGH_ERR event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
0	VAC_INSERT_MASK	0	N	Y	RW	Masks a VAC_INSERT event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask

Register Address: 0x000F, Register Name: INT_FLAG3

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBUS_ INSERT_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{BUS} is over than V_{BUS_INSERT} threshold. 0: No VBUS_INSERT. 1: VBUS_INSERT has occurred. (Clear upon read.)
6	VOUT_ INSERT_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{OUT} is over than V_{OUT_INSERT} threshold. 0: No VOUT_INSERT. 1: VOUT_INSERT has occurred. (Clear upon read.)
5	WDT_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when a watchdog time out event occurs. 0: No watchdog time out. 1: Watchdog time out has occurred. (Clear upon read.)
4	VAC_UVLO_ FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{AC} is lower than V_{AC_INSERT} threshold. 0: No VAC_UVLO. 1: VAC_UVLO has occurred. (Clear upon read.)
3	VBUS_UVLO_ FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{BUS} is lower than V_{BUS_INSERT} threshold. 0: No VBUS_UVLO. 1: VBUS_UVLO has occurred. (Clear upon read.)
2	IBUS_UCP_ TIMEOUT_ FLAG	0	N	N	RC	If I_{BUS} is not ramped to the $I_{BUS\_UCP\_RISE}$ threshold in IBUS_UCP_TIMEOUT time after CHG_EN = 1, the converter will stop switching. Set 1 and send an $\overline{INT}$ when this event happens. 0: No IBUS_UCP_TIMEOUT. 1: IBUS_UCP_TIMEOUT has occurred. (Clear upon read.)
1	ADC_DONE_ FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when ADC conversion is completed in 1-shot mode. 0: No ADC conversion. 1: ADC conversion is completed. (Clear upon read.)
0	CFLY_DIAG_ FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when CFLY short during converter soft-start. 0: No CFLY short. 1: CFLY short has occurred. (Clear upon read.)

Register Address: 0x0010, Register Name: INT_MASK3

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBUS_INSERT_MASK	0	N	Y	RW	Masks a VBUS_INSERT event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
6	VOUT_INSERT_MASK	0	N	Y	RW	Masks a VOUT_INSERT event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
5	WDT_MASK	0	N	Y	RW	Masks a watchdog time out event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
4	VAC_UVLO_MASK	0	N	Y	RW	Masks a VAC_UVLO event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
3	VBUS_UVLO_MASK	0	N	Y	RW	Masks a VBUS_UVLO event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
2	IBUS_UCP_TIMEOUT_MASK	0	N	Y	RW	Masks a IBUS_UCP_TIMEOUT event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
1	ADC_DONE_MASK	0	N	Y	RW	Masks a ADC conversion event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
0	CFLY_DIAG_MASK	0	N	Y	RW	Masks a CFLY short event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask

Register Address: 0x0011, Register Name: ADC_CTRL

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	ADC_EN	0	Y	Y	RW	Enable ADC conversion. 0: Disable (default) 1: Enable
6	ADC_RATE	0	N	Y	RW	ADC conversion rate 0: Continuous mode (default) 1: 1-shot mode (In 1-shot mode, ADC_EN will be reset to 0 after ADC conversion is completed.)
5	VBUS_ADC_DIS	0	N	Y	RW	Disable VBUS_ADC. 0: Enable Conversion (default) 1: Disable Conversion
4	IBUS_ADC_DIS	0	N	Y	RW	Disable IBUS_ADC. 0: Enable Conversion (default) 1: Disable Conversion
3	VBAT_ADC_DIS	0	N	Y	RW	Disable VBAT_ADC. 0: Enable Conversion (default) 1: Disable Conversion
2	IBAT_ADC_DIS	0	N	Y	RW	Disable IBAT_ADC. 0: Enable Conversion (default) 1: Disable Conversion
1	TDIE_ADC_DIS	0	N	Y	RW	Disable TDIE_ADC. 0: Enable Conversion (default) 1: Disable Conversion
0	Reserved	0	NA	NA	NA	Reserved

Register Address: 0x0012, Register Name: VBUS_ADC1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:6	Reserved	00	NA	NA	NA	Reserved
5:0	VBUS_ADC1	000000	N	N	R	VBUS ADC high byte HSB<5:0>: 8192mV, 4096mV, 2048mV, 1024mV, 512mV, 256mV

Register Address: 0x0013, Register Name: VBUS_ADC0

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:0	VBUS_ADC0	00000000	N	N	R	VBUS ADC low byte LSB<7:0>: 128mV, 64mV, 32mV, 16mV, 8mV, 4mV, 2mV, 1mV

Register Address: 0x0014, Register Name: IBUS_ADC1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:6	Reserved	00	NA	NA	NA	Reserved
5:0	IBUS_ADC1	000000	N	N	R	IBUS ADC high byte HSB<5:0>: 8192mA, 4096mA, 2048mA, 1024mA, 512mA, 256mA

Register Address: 0x0015, Register Name: IBUS_ADC0

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:0	IBUS_ADC0	00000000	N	N	R	IBUS ADC low byte LSB<7:0>: 128mA, 64mA, 32mA, 16mA, 8mA, 4mA, 2mA, 1mA

Register Address: 0x0016, Register Name: VBAT_ADC1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:6	Reserved	00	NA	NA	NA	Reserved
5:0	VBAT_ADC1	000000	N	N	R	VBAT ADC high byte HSB<5:0>: 8192mV, 4096mV, 2048mV, 1024mV, 512mV, 256mV

Register Address: 0x0017, Register Name: VBAT_ADC0

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:0	VBAT_ADC0	00000000	N	N	R	VBAT ADC low byte LSB<7:0>: 128mV, 64mV, 32mV, 16mV, 8mV, 4mV, 2mV, 1mV

Register Address: 0x0018, Register Name: IBAT_ADC1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:6	Reserved	00	NA	NA	NA	Reserved
5:0	IBAT_ADC1	000000	N	N	R	IBAT ADC high byte HSB<5:0>: 8192mA,4096mA, 2048mA, 1024mA, 512mA, 256mA

Register Address: 0x0019, Register Name: IBAT_ADC0

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:0	IBAT_ADC0	00000000	N	N	R	IBAT ADC low byte LSB<7:0>: 128mA, 64mA, 32mA, 16mA, 8mA, 4mA, 2mA, 1mA

Register Address: 0x001A, Register Name: TDIE_ADC0

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:0	TDIE_ADC	00000000	N	N	R	TDIE ADC LSB<7:0>: 128°C, 64°C, 32°C, 16°C, 8°C, 4°C, 2°C, 1°C TDIE = –40°C + TDIE_ADC<7:0> x 1°C

Register Address: 0x0044, Register Name: BC12_CTL

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	BC12_EN	0	Y	Y	RW	Enable BC1.2 detection. 0: Disable BC1.2 detection (default) 1: Enable BC1.2 detection (BC1.2 detection cannot be enable if DP_SYNCOUT_CFG = 1, DM_TS_CFG = 1)
6:5	DCD_ TIMEOUT_ SET	01	Y	Y	RW	BC1.2 data contact timer. 00: Disable DCD timeout function 01: Enable 600ms DCD timeout function (default) 10: Enable 900ms DCD timeout function 11: Wait data contact
4	VLGC_OPT	0	Y	Y	RW	Enable primary detection high reference voltage option. 0: Disable (default) 1: Enable
3:2	HOST_MODE	00	Y	Y	RW	Host mode setting in OTG. 00: DPDM floating (default) 01: SDP 10: CDP 11: DCP
1:0	Reserved	00	NA	NA	NA	Reserved

Register Address: 0x0045, Register Name: BC12_FLAG1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:4	Reserved	0000	NA	NA	NA	Reserved
3	BC12_DONE_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when BC1.2 detection done. 0: BC1.2 detection not ready 1: BC12_DONE_STAT rising detection done (Clear upon read.)
2	DCDT_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when data contact detection fail in DCD_TIMEOUT time. 0: DCD Timeout event of BC1.2 detection not occurs 1: DCD Timeout event of BC1.2 detection occurs (Clear upon read.)
1	CDP_DONE_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when CDP flow done. 0: No CDP flow 1: CDP flow done (This bit will be updated when HOST mode is changed.) (Clear upon read.)
0	CDP_PD_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when CDP primary detection start. 0: CDP primary detection does not start 1: CDP primary detection starts (This bit will be updated when HOST mode is changed.) (Clear upon read.)

Register Address: 0x0046, Register Name: BC12_STAT1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:5	USB_STATUS	000	N	Y	R	000: No VBUS 001: VBUS flow is under going 010: SDP 011: NSTD 100: DCP 101: CDP 110: Reserved 111: Reserved
4	Reserved	0	NA	NA	NA	Reserved
3	BC12_DONE_STAT	0	N	N	R	BC12 status bit 0: BC12 NOT complete 1: BC12 complete
2	Reserved	0	NA	NA	NA	Reserved
1	CDP_DONE_STAT	0	N	N	R	CDP flow done 0: No CDP flow 1: CDP flow done. (This bit will be updated when HOST mode is changed.)
0	CDP_PD_STAT	0	N	N	R	CDP primary detection start. 0: CDP primary detection does not start 1: CDP primary detection started (This bit will be updated when HOST mode is changed.)

Register Address: 0x0047, Register Name: BC12_MASK1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:4	Reserved	0000	NA	NA	NA	Reserved
3	BC12_DONE_MASK	0	N	Y	RW	Masks a BC12_DONE event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
2	DCDT_MASK	0	N	Y	RW	Masks a DCDT event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
1	CDP_DONE_MASK	0	N	Y	RW	Masks a CDP_DONE event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
0	CDP_PD_MASK	0	N	Y	RW	Masks a CDP_PD event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask

Register Address: 0x0048, Register Name: DPDM_CTL

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	SET_DPDM_EN	0	N	Y	RW	Enable DP, DM voltage setting function. 0: Disable DP, DM set function (default) 1: Enable DP, DM set function
6:4	SET_DP	000	N	Y	RW	DP output voltage selection. 000: Set DP to HZ (default) 001: Set DP to 0 V 010: Set DP to 0.6V 011: Set DP to 1.8V 100: Set DP to 2.8V 101: Set DP to 3.3V 110 to 111: Reserved
3:1	SET_DM	000	N	Y	RW	DM output voltage selection. 000: Set DM to HZ (default) 001: Set DM to 0 V 010: Set DM to 0.6V 011: Set DM to 1.8V 100: Set DM to 2.8V 101: Set DM to 3.3V 110 to 111: Reserved
0	VAC_INSERT_PROTOCOL_DIS	0	N	Y	RW	0: DPDM protocol can be enable with VAC_INSERT_STATUS = 1 (default) 1: DPDM protocol can be enable with VAC_INSERT_STATUS = 1 or 0

Register Address: 0x0049, Register Name: INT_FLAG4

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBAT_OVP_ ALM_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{BAT} is over than $V_{BAT\_OVP\_ALM}$ threshold. 0: No VBAT_OVP_ALM Fault 1: VBAT_OVP_ALM Fault has occurred (Clear upon read.)
6	IBAT_OCP_ ALM_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when I_{BAT} is over than $I_{BAT\_OCP\_ALM}$ threshold. 0: No IBAT_OCP_ALM Fault 1: IBAT_OCP_ALM Fault has occurred (Clear upon read.)
5	VBUS_OVP_ ALM_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{BUS} is over than $V_{BUS\_OVP\_ALM}$ threshold. 0: No VBUS_OVP_ALM Fault 1: VBUS_OVP_ALM Fault has occurred (Clear upon read.)
4	IBUS_OCP_ ALM_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when I_{BUS} is over than $I_{BUS\_OCP\_ALM}$ threshold. 0: No IBUS_OCP_ALM Fault 1: IBUS_OCP_ALM Fault has occurred (Clear upon read.)
3	IBAT_UCP_ ALM_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when I_{BAT} current is lower than $I_{BAT\_UCP\_ALM}$ threshold. 0: No IBAT_UCP_ALM rising 1: IBAT_UCP_ALM rising has occurred (Clear upon read.)
2	IBUS_UCP_ ALM_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when I_{BUS} current is lower than $I_{BUS\_UCP\_ALM}$ threshold. 0: No IBUS_UCP_ALM rising 1: IBUS_UCP_ALM rising has occurred (Clear upon read.)
1	TDIE_OTP_ ALM_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when die temperature is over than T_{DIE_ALM} threshold. 0: No TDIE_OTP_ALM Fault 1: TDIE_OTP_ALM Fault has occurred (Clear upon read.)
0	VOUT_OVP_ FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when V_{OUT} is over than V_{OUT_OVP} threshold. 0: No VOUT_OVP Fault 1: VOUT_OVP Fault has occurred (Clear upon read.)

Register Address: 0x004A, Register Name: INT_MASK4

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBAT_OVP_ ALM_MASK	0	N	Y	RW	Masks a VBAT_OVP_ALM event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
6	IBAT_OCP_ ALM_MASK	0	N	Y	RW	Masks a IBAT_OCP_ALM event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
5	VBUS_OVP_ ALM_MASK	0	N	Y	RW	Masks a VBUS_OVP_ALM event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
4	IBUS_OCP_ ALM_MASK	0	N	Y	RW	Masks a IBUS_OCP_ALM event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
3	IBAT_UCP_ ALM_MASK	0	N	Y	RW	Masks a IBAT_UCP_ALM event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
2	IBUS_UCP_ ALM_MASK	0	N	Y	RW	Masks a IBUS_UCP_ALM event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
1	TDIE_OTP_ ALM_MASK	0	N	Y	RW	Masks a TDIE_OTP_ALM event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
0	VOUT_OVP_ MASK	0	N	N	RW	Masks a VOUT_OVP event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask

Register Address: 0x004B, Register Name: INT_STAT1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VAC_OVP_STAT	0	N	N	R	Set 1 when a VAC_OVP event occurs. Persists until condition is no longer valid. 0: No VAC_OVP Fault 1: VAC_OVP Fault has occurred.
6:5	Reserved	00	NA	NA	NA	Reserved
4	VDR_OVP_STAT	0	N	N	R	Set 1 when a VDR_OVP has occurred. Persists until condition is no longer valid. 0: No VDR_OVP Fault 1: VDR_OVP Fault has occurred.
3	VBUS_OVP_STAT	0	N	N	R	Set 1 when V_{BUS} is over than V_{BUS_OVP} threshold. Persists until condition is no longer valid. 0: No VBUS_OVP Fault 1: VBUS_OVP Fault has occurred.
2	IBUS_OCP_STAT	0	N	N	R	Set 1 when I_{BUS} is over than I_{BUS_OCP} threshold. Persists until condition is no longer valid. 0: No IBUS_OCP Fault 1: IBUS_OCP Fault has occurred.
1:0	Reserved	00	NA	NA	NA	Reserved

Register Address: 0x004C, Register Name: INT_STAT2

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBAT_OVP_STAT	0	N	N	R	Set 1 when V_{BAT} is over than V_{BAT_OVP} threshold. Persists until condition is no longer valid. 0: No VBAT_OVP Fault. 1: VBAT_OVP Fault has occurred.
6	IBAT_OCP_STAT	0	N	N	R	Set 1 when I_{BAT} is over than I_{BAT_OCP} threshold. Persists until condition is no longer valid. 0: No IBAT_OCP Fault. 1: IBAT_OCP Fault has occurred.
5	VBAT_REG_STAT	0	N	N	R	Set 1 when VBAT_REG has been active. Persists until condition is no longer valid. 0: No VBAT_REG. 1: VBAT_REG has occurred.
4	IBAT_REG_STAT	0	N	N	R	Set 1 when IBAT_REG has been active. Persists until condition is no longer valid. 0: No IBAT_REG. 1: IBAT_REG has occurred.
3	TDIE_OTP_STAT	0	N	N	R	Set 1 when die temperature is over than T_{DIE} threshold. Persists until condition is no longer valid. 0: No TDIE_OTP Fault. 1: TDIE_OTP Fault has occurred.
2	VBUS_LOW_ERR_STAT	0	N	N	R	Set 1 when V_{BUS} voltage is lower $V_{BUS\_LOW\_ERR}$ threshold. Persists until condition is no longer valid. 0: No VBUS_LOW_ERR Fault 1: VBUS_LOW_ERR Fault has occurred.
1	VBUS_HIGH_ERR_STAT	0	N	N	R	Set 1 when V_{BUS} voltage is over $V_{BUS\_HIGH\_ERR}$ threshold. Persists until condition is no longer valid. 0: No VBUS_HIGH_ERR Fault. 1: VBUS_HIGH_ERR Fault has occurred.
0	VAC_INSERT_STAT	0	N	N	R	Set 1 when V_{AC} is over than V_{AC_INSERT} threshold. Persists until condition is no longer valid. 0: No VAC_INSERT. 1: VAC_INSERT has occurred.

Register Address: 0x004D, Register Name: INT_STAT3

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBUS_ INSERT_STAT	0	N	N	R	Set 1 when V_{BUS} is over than V_{BUS_INSERT} threshold. Persists until condition is no longer valid. 0: No VBUS_INSERT. 1: VBUS_INSERT has occurred.
6	VOUT_ INSERT_STAT	0	N	N	R	Set 1 when V_{OUT} is over than V_{OUT_INSERT} threshold. Persists until condition is no longer valid. 0: No VOUT_INSERT 1: VOUT_INSERT has occurred.
5	Reserved	0	NA	NA	NA	Reserved
4	VAC_UVLO_ STAT	0	N	N	R	Set 1 when V_{AC} is lower than V_{AC_INSERT} threshold. Persists until condition is no longer valid. 0: No VAC_UVLO. 1: VAC_UVLO has occurred.
3	VBUS_UVLO_ STAT	0	N	N	R	Set 1 when V_{BUS} is lower than V_{BUS_INSERT} threshold. Persists until condition is no longer valid. 0: No VBUS_UVLO. 1: VBUS_UVLO has occurred.
2	IBUS_UCP_ TIMEOUT_ STAT	0	N	N	R	Set 1 when IBUS_UCP_TIMEOUT is occurring. Persists until condition is no longer valid. 0: No IBUS_UCP_TIMEOUT. 1: IBUS_UCP_TIMEOUT is occurring.
1	ADC_DONE_ STAT	0	N	N	R	Set 1 when the ADC conversion is completed in 1-shot mode. This bit will change to '0' when an ADC conversion is requested in 1-shot mode, and it will change back to '1' when the conversion is complete. During continuous conversion mode, this bit will be '0' 0: Conversion not complete. 1: Conversion complete.
0	Reserved	0	NA	NA	NA	Reserved

Register Address: 0x004E, Register Name: INT_STAT4

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBAT_OVP_ ALM_STAT	0	N	N	R	Set 1 when V_{BAT} is over than $V_{BAT\_OVP\_ALM}$ threshold. Persists until condition is no longer valid. 0: No VBAT_OVP_ALM Fault 1: VBAT_OVP_ALM Fault has occurred.
6	IBAT_OCP_ ALM_STAT	0	N	N	R	Set 1 when I_{BAT} is over than $I_{BAT\_OCP\_ALM}$ threshold. Persists until condition is no longer valid. 0: No IBAT_OCP_ALM Fault 1: IBAT_OCP_ALM Fault has occurred.
5	VBUS_OVP_ ALM_STAT	0	N	N	R	Set 1 when V_{BUS} is over than $V_{BUS\_OVP\_ALM}$ threshold. Persists until condition is no longer valid. 0: No VBUS_OVP_ALM Fault 1: VBUS_OVP_ALM Fault has occurred.
4	IBUS_OCP_ ALM_STAT	0	N	N	R	Set 1 when I_{BUS} is over than $I_{BUS\_OCP\_ALM}$ threshold. Persists until condition is no longer valid. 0: No IBUS_OCP_ALM Fault 1: IBUS_OCP_ALM Fault has occurred.
3	IBAT_UCP_ ALM_STAT	0	N	N	R	Set 1 when I_{BAT} current is lower than $I_{BAT\_UCP\_ALM}$ threshold. Persists until condition is no longer valid. 0: No IBAT_UCP_ALM rising 1: IBAT_UCP_ALM rising has occurred.
2	IBUS_UCP_ ALM_STAT	0	N	N	R	Set 1 when I_{BUS} current is lower than $I_{BUS\_UCP\_ALM}$ threshold. Persists until condition is no longer valid. 0: No IBUS_UCP_ALM rising 1: IBUS_UCP_ALM rising has occurred.
1	TDIE_OTP_ ALM_STAT	0	N	N	R	Set 1 when die temperature is over than $T_{DIE\_OTP\_ALM}$ threshold. Persists until condition is no longer valid. 0: No TDIE_OTP_ALM Fault 1: TDIE_OTP_ALM Fault has occurred.
0	VOUT_OVP_ STAT	0	N	N	R	Set 1 when V_{OUT} is over than V_{OUT_OVP} threshold. Persists until condition is no longer valid. 0: No VOUT_OVP Fault 1: VOUT_OVP Fault has occurred.

Register Address: 0x004F, Register Name: VBAT_OVP_ALM

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBAT_OVP_ALM_DIS	0	N	Y	RW	Disable VBAT_OVP_ALM. 0: Enable (default) 1: Disable
6:5	Reserved	00	NA	NA	NA	Reserved
4:0	VBAT_OVP_ALM	00000	N	Y	RW	Battery overvoltage alarm threshold. $V_{BAT\_OVP\_ALM}$ = 4.2V + VBAT_OVP_ALM[4:0] x 25mV Default: 4.2V (b00000)

Register Address: 0x0050, Register Name: IBAT_OCP_ALM

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	IBAT_OCP_ALM_DIS	0	N	Y	RW	Disable IBAT_OCP_ALM. 0: Enable (default) 1: Disable
6	Reserved	0	NA	NA	NA	Reserved
5:0	IBAT_OCP_ALM	110010	N	Y	RW	Battery overcurrent alarm threshold. $I_{BAT\_OCP\_ALM}$ = 2A + IBAT_OCP_ALM[5:0] X 100mA Default: 7A (b110010)

Register Address: 0x0051, Register Name: VBUS_OVP_ALM

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VBUS_OVP_ALM_DIS	0	N	Y	RW	Disable VBUS_OVP_ALM. 0: Enable (default) 1: Disable
6	Reserved	0	NA	NA	NA	Reserved
5:0	VBUS_OVP_ALM	011100	N	Y	RW	VBUS overvoltage alarm threshold. The setting is determined by difference modes. Device in DIV2 mode: V_{BUS_OVP} = 6V + VBUS_OVP[5:0] x 100mV, Default: 8.8V (b011100) Device in BYPASS mode: V_{BUS_OVP} = 3V + VBUS_OVP[5:0] x 50mV, Default: 4.4V (b011100)

Register Address: 0x0052, Register Name: IBUS_OCP_ALM

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	IBUS_OCP_ALM_DIS	0	N	Y	RW	Disable IBUS_OCP_ALM. 0: Enable (default) 1: Disable
6	Reserved	0	NA	NA	NA	Reserved
5:0	IBUS_OCP_ALM	011100	N	Y	RW	IBUS overcurrent alarm threshold. The setting is determined by $I_{BUS\_OCP\_ALM}$ = IBUS_OCP_ALM[5:0] x 100mA. Default: 2.8A (b011100)

Register Address: 0x0053, Register Name: IBAT_UCP_ALM

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	IBAT_UCP_ALM_DIS	0	N	Y	RW	Disable IBAT_UCP_ALM. 0: Enable (default) 1: Disable
6	Reserved	0	NA	NA	NA	Reserved
5:0	IBAT_UCP_ALM	101000	N	Y	RW	IBAT undercurrent alarm threshold. $I_{BAT\_UCP\_ALM}$ = IBAT_UCP_ALM [5:0] x 50mA Default: 2A (b101000)

Register Address: 0x0054, Register Name: IBUS_UCP_ALM

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	IBUS_UCP_ALM_DIS	0	N	Y	RW	Disable IBUS_UCP_ALM. 0: Enable (default) 1: Disable
6:0	IBUS_UCP_ALM	0101000	N	Y	RW	IBUS undercurrent alarm threshold. $I_{BUS\_UCP\_ALM}$ = IBUS_UCP_ALM [6:0] x 25mA Default: 1A (b0101000)

Register Address: 0x0055, Register Name: TDIE_OTP_ALM

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	TDIE_OTP_ALM_DIS	0	N	Y	RW	Disable TDIE_OTP_ALM. 0: Enable (default) 1: Disable
6:0	TDIE_OTP_ALM	1100100	N	Y	RW	TDIE alarm threshold. T_{DIE_ALM} = 25°C + TDIE_ALM[6:0] x 1°C Default: 125°C (b1100100)

Register Address: 0x0056, Register Name: VOUT_ADC1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	VOUT_ADC_DIS	0	N	Y	RW	Disable VOUT_ADC. 0: Enable conversion (default) 1: Disable conversion
6	Reserved	0	NA	NA	NA	Reserved
5:0	VOUT_ADC1	000000	N	N	R	VOUT ADC high byte HSB<5:0>: 8192mV, 4096mV, 2048mV, 1024mV, 512mV, 256mV

Register Address: 0x0057, Register Name: VOUT_ADC0

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:0	VOUT_ADC0	00000000	N	N	R	VOUT ADC low byte LSB<7:0>: 128mV, 64mV, 32mV, 16mV, 8mV, 4mV, 2mV, 1mV

Register Address: 0x0058, Register Name: DP_ADC1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	DP_ADC_DIS	1	N	Y	RW	Disable DP ADC. 0: Enable 1: Disable (default)
6	Reserved	0	NA	NA	NA	Reserved
5:0	DP_ADC1	000000	N	Y	R	DP ADC high byte HSB<5:0>: 8192mV, 4096mV, 2048mV, 1024mV, 512mV, 256mV

Register Address: 0x0059, Register Name: DP_ADC0

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:0	DP_ADC0	00000000	N	Y	R	DP ADC LSB<7:0>: 128mV, 64mV, 32mV, 16mV, 8mV, 4mV, 2mV, 1mV

Register Address: 0x005A, Register Name: DM_ADC1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	DM_ADC_DIS	1	N	Y	RW	Disable DM ADC. 0: Enable 1: Disable (default)
6	Reserved	0	NA	NA	NA	Reserved
5:0	DM_ADC1	000000	N	Y	R	DM ADC high byte HSB<5:0>: 8192mV, 4096mV, 2048mV, 1024mV, 512mV, 256mV

Register Address: 0x005B, Register Name: DM_ADC0

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:0	DM_ADC0	00000000	N	Y	R	DM ADC low byte LSB<7:0>: 128mV, 64mV, 32mV, 16mV, 8mV, 4mV, 2mV, 1mV

Register Address: 0x005C, Register Name: CON_STAT

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	CON_ SWITCHING_ STAT	0	N	N	R	Set 1 and send an $\overline{INT}$ when the converter start switching and IBUS_UCP_TIMEOUT timer start. Only one $\overline{INT}$ is sent when switching starts. Persists until condition is no longer valid. 0: No CON_SWITCHING 1: SWITCHING is occurring.
6	CON_ SWITCHING_ MASK	0	N	N	RW	Masks a CON_SWITCHING event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
5:4	IC_STAT	00	N	N	R	Indicate converter operation status. 00: Standby mode 01: Bypass mode 10: Forward DIV2 mode 11: Reserved
3:0	Reserved	0000	NA	NA	NA	Reserved

Register Address: 0x005D, Register Name: IBUS_UCP_TIMEOUT

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:5	IBUS_UCP_ TIMEOUT	111	N	Y	RW	Adjustable timeout for I_{BUS} to rise to $I_{BUS\_UCP\_RISE}$ threshold. 000: Timeout disabled 001: 12.5ms 010: 25ms 011: 50ms 100: 100ms 101: 400ms 110: 1.5s 111: 100s (default)
4	Reserved	0	NA	NA	NA	Reserved
3	IBUS_UCP_ FALL_ DEGLITCH_ SET	0	N	Y	RW	This bit sets the deglitch time for VBUS_UCP_FALL. 0: 22μs (default) 1: 5ms
2:0	Reserved	000	NA	NA	NA	Reserved

Register Address: 0x005E, Register Name: other1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	EN_I2C_ LEVEL_ DETECTION	1	NA	NA	RW	0: Disable 1: Enable (default)
6	I2C_level	1	NA	NA	RW	0: 1.8V 1: 1.2V (default)
5:4	Reserved	00	NA	NA	NA	Reserved
3	VOUT_OVP_ EN	1	N	Y	RW	Enable VOUT overvoltage protection. 0: Disable 1: Enable (default)
2	Reserved	1	NA	NA	NA	Reserved
1:0	IBAT_RSEN	01	N	N	RW	This bit selects the external battery current sense resistor value. 00: 1mΩ 01: 2mΩ (default) 10: 5mΩ 11: 10mΩ

Register Address: 0x005F, Register Name: other2

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	DP_SYNCOUT _CFG	0	N	N	RW	DP_SYNCOUT pin configuration. 0: DP_SYNCOUT pin is configured as DP pin. (default) 1: DP_SYNCOUT pin is configured as SYNCOUT pin. (All DP pin functions are invalid when DP_SYNCOUT = 1.)
6	DM_TS_CFG	0	N	N	RW	DM_TS pin configuration. 0: DM_TS pin is configured as DM pin. (default) 1: DM_TS pin is configured as TS pin. (All TS functions are invalid when DM_TS = 0. All DM pin functions are invalid when DM_TS = 1.)
5	BATN_SRP_ SYNCIN_CFG	0	N	N	RW	BATN/SRP_SYNCIN pin configuration 0: BATN/SRP_SYNCIN pin is configured as BATN/SRP pin. (default) 1: BATN/SRP_SYNCIN pin is configured as SYNCIN pin. (All sensing and protection of VBAT and IBAT are invalid when BATN/SRP_SYNCIN = 1.)
4	Reserved	0	NA	NA	NA	Reserved
3	TS_OTP_ FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when TS ADC is lower than TS_OTP threshold. 0: No TS_OTP 1: TS_OTP has occurred. (Clear upon read.)
2	TS_OTP_ MASK	0	N	Y	RW	Masks a TS_OTP event to send an $\overline{INT}$ 0: Unmask (default) 1: Mask
1	TS_OTP_ STAT	0	N	N	R	Set 1 when TS ADC is lower than TS_OTP threshold. Persists until condition is no longer valid. 0: No TS_OTP 1: TS_OTP has occurred.
0	TS_OTP_EN	0	N	Y	RW	Enable TS_OTP. 0: Disable (default) 1: Enable

Register Address: 0x0060, Register Name: TS_OTP

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:0	TS_OTP	00000000	N	Y	RW	TS_OTP Threshold TS_OTP = TS_OTP[7:0] x 7mV Default: 0V (b00000000)

Register Address: 0x0061, Register Name: DPDM_OV_ALM

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	DP_OV_ALM_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when DP_ADC is over than 4.5V. 0: No DP_OV_ALM Fault 1: DP_OV_ALM Fault has occurred. (Clear upon read.)
6	DM_OV_ALM_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when DM_ADC is over than 4.5V. 0: No DM_OV_ALM Fault 1: DM_OV_ALM Fault has occurred. (Clear upon read.)
5	DP_OV_ALM_STAT	0	N	N	R	DP_OV_ALM status when DP_ADC is over than 4.5V. Persists until condition is no longer valid. 0: No DP_OV_ALM fault 1: DP_OV_ALM fault has occurred.
4	DM_OV_ALM_STAT	0	N	N	R	DM_OV_ALM status when DM_ADC is over than 4.5V. Persists until condition is no longer valid. 0: No DM_OV_ALM fault 1: DM_OV_ALM fault has occurred.
3	DP_OV_ALM_MASK	0	N	Y	RW	Masks a DP_OV_ALM event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
2	DM_OV_ALM_MASK	0	N	Y	RW	Masks a DM_OV_ALM event to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
1	IBUS_OCP_H_MASK	0	N	Y	RW	Masks a IBUS_OCP_H to send an $\overline{INT}$. 0: Unmask (default) 1: Mask
0	IBUS_OCP_H_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$, when IBUS_OCP_H trigger. 0: No IBUS_OCP_H fault. 1: IBUS_OCP_H Fault has occurred. (Clear upon read)

Register Address: 0x0062, Register Name: REVISION

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:2	Reserved	000000	NA	NA	NA	Reserved
1:0	PRODUCT_ID	01	N	N	RO	01: RT9756A

Register Address: 0x0063, Register Name: other3

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:3	Reserved	00000	NA	NA	NA	Reserved
2	CHIP_RESET_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when power-on ready. 0: No power-on ready fault. 1: Power-on ready has occurred. (Clear upon read.)
1	VDDA_UVLO_FLAG	0	N	N	RC	Set 1 and send an $\overline{INT}$ when trigger VDDA_UVLO. 0: No VDDA_UVLO fault. 1: VDDA_UVLO fault has occurred. (Clear upon read.)
0	VDDA_UVLO_MASK	0	N	Y	RW	Masks a VDDA_UVLO to send an $\overline{INT}$. 0: Unmask (default) 1: Mask

Register Address: 0x0066, Register Name: DPDM_SEL1

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7:6	DP_DISCHG_SEL	11	N	Y	RW	DP discharge level selection when SET_DPDM_EN = 1. 00: Bypass 01: 20kΩ 10: 45μA 11: 60μA (default)
5:4	DM_DISCHG_SEL	11	N	Y	RW	DM discharge level selection when SET_DPDM_EN = 1. 00: Bypass 01: 20kΩ 10: 45μA 11: 60μA (default)
3:2	DP_PULL_SEL	11	N	Y	RW	DP pull-up resistor level selection when SET_DPDM_EN = 1. 00: 1.2kΩ 01: 2.7kΩ 10: 15kΩ 11: Bypass (default)
1:0	DM_PULL_SEL	11	N	Y	RW	DM pull-up resistor level selection when SET_DPDM_EN = 1. 00: 1.2kΩ 01: 2.7kΩ 10: 15kΩ 11: Bypass (default)

Register Address: 0x006D, Register Name: DPDM_CON5

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	DP_DISCHG_EN	0	N	Y	RW	DP discharge current or resistor enable control when SET_DPDM_EN = 1. 0: Disable (default) 1: Enable
6:4	Reserved	110	NA	NA	NA	Reserved
3	DM_DISCHG_EN	0	N	Y	RW	DM discharge current or resistor enable control when SET_DPDM_EN = 1. 0: Disable (default) 1: Enable
2:0	Reserved	110	NA	NA	NA	Reserved

Register Address: 0x006E, Register Name: DPDM_CON6

Bit	Bit Name	Default	WDT RST	REG RST	Type	Description
7	DP_PULL_IEN	0	N	Y	RW	DP pull-up current source enable control when SET_DPDM_EN = 1. 0: Disable (default) 1: Enable (10μA)
6	DP_PULL_REN	0	N	Y	RW	DP pull-up resistor enable control when SET_DPDM_EN = 1. 0: Disable (default) 1: Enable
5:4	Reserved	11	NA	NA	NA	Reserved
3	DM_PULL_IEN	0	N	Y	RW	DM pull-up current source enable control when SET_DPDM_EN = 1. 0: Disable (default) 1: Enable (10μA)
2	DM_PULL_REN	0	N	Y	RW	DM pull-up resistor enable control when SET_DPDM_EN = 1. 0: Disable (default) 1: Enable
1:0	Reserved	110	NA	NA	NA	Reserved

Application Information

Richtek's component specification does not include the following information in the Application Information section. Thereby no warranty is given regarding its validity and accuracy. Customers should take responsibility to verify their own designs and reserve suitable design margin to ensure the functional suitability of their components and systems.

Operation Principle

The cap divider topology relies on a smart wall adapter to control the voltage and current of input in order to charge. Based on the cap divider topology, the 4 MOSFETs (Q1 to Q4) are used to charge and discharge flying capacitor (CFLY) alternately. The simplified circuit of cap divider is shown in Figure 1(A).

In period 1: When Q1 and Q3 are turned on and Q2 and Q4 are turned off, the CFLY and BAT are in series with VBUS. The BUS current is supplied to COUT and BAT directly. During this period, the voltage of CFLY can be expressed as equation 1:

$V_{CFLY} = V_{BUS} - V_{BAT}$ ---- (1)

In period 2: When Q1 and Q3 are turned off and Q2 and Q4 are turned on, the CFLY and BAT are in parallel. The current of BAT is only supplied by CFLY. During this period, the voltage of CFLY can be expressed as equation 2:

$V_{CFLY} = V_{BAT}$ ---- (2)

If the equation 2 is substituted into equation 1, the equation 1 can be expressed as equation 3:

$V_{BAT} = V_{BUS} / 2$ ---- (3)

If the power dissipation of topology is ignored, the output power can be expressed as equation 4:

$V_{BAT} \times I_{BAT} = V_{BUS} \times I_{BUS}$ --- (4)

If the equation 3 is substituted into equation 4, the IBAT can be expressed as equation 5:

$I_{BAT} = 2 \times I_{BUS}$ --- (5)

According to the equations above, the battery voltage is half of the input voltage and the current flow into the battery is twice the input current in cap divider topology. For the efficiency and output ripple improvement in application, the dual phase cap divider topology with phase shift 180-degree between phases are built in the RT9756A.

The RT9756A also has Bypass mode for direct charging. To use Bypass mode, set OPERATION_MODE (0x0000[5]) = 0 before start charging. In the Bypass mode, Q1, Q2 and Q4 turn on continuously as shown in Figure 1(B).

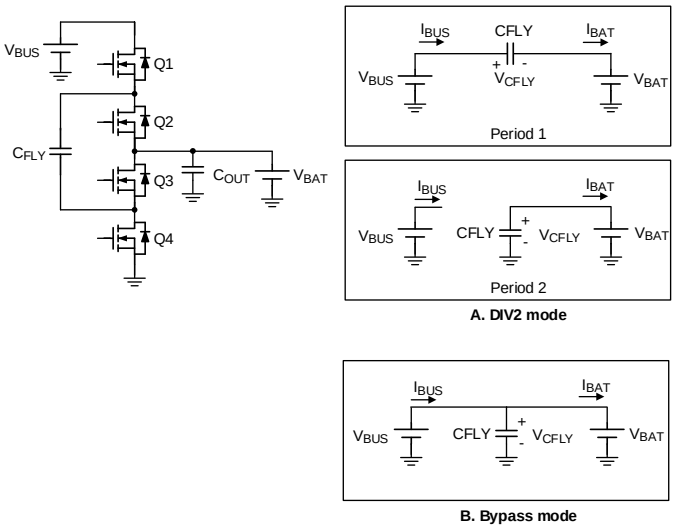


Figure 1. Simplified Circuit of Cap Divider

Charge System Introduction

The RT9756A is a smart cap divider charger used in slave charger application. The RT9756A generates high output current with cap divider topology. Before enabling the RT9756A, the host sets up all of protection and alarm functions and disables main charger in power solution. The host must monitor the alarms that set up in RT9756A during high current charging period and communicate with the smart wall adapter to control the charging current flow into the battery.

Figure 2 is the simplified charge system block. In this charge system, RT9756A is used to detect USB BC1.2 of adapter and the PD controller is used to communicate with adapter by PD protocol. Once the smart wall adapter is detected, the AP will control the switching charger and smart cap divider charger to achieve high current charging period. These devices can communicate with each other through I^2C serial interface.

The charge profile of high capacity battery using switching charger and cap divider charger is shown in Figure 3. In order to achieve the charge profile, the switching charger is required to dominate pre-charge, fast charge when battery voltage is lower than system startup voltage, constant voltage and termination periods, respectively. The cap divider charger is used to achieve fast charge period. To shorten the constant voltage period, the cap divider charger is controlled to reduce the charge current by ramp step when battery voltage triggers the VBAT_OVP_ALM.

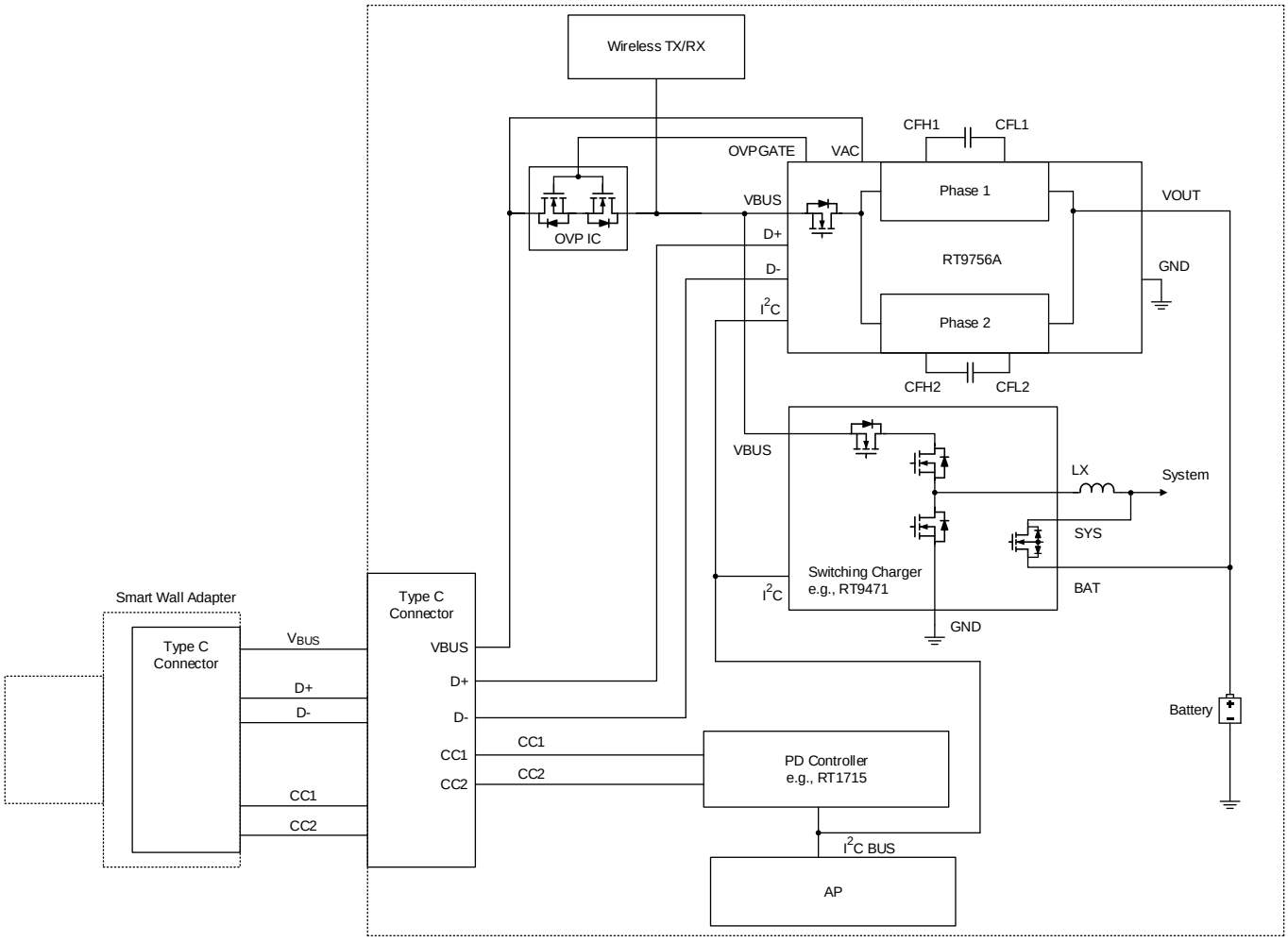


Figure 2. Simplified Charge System

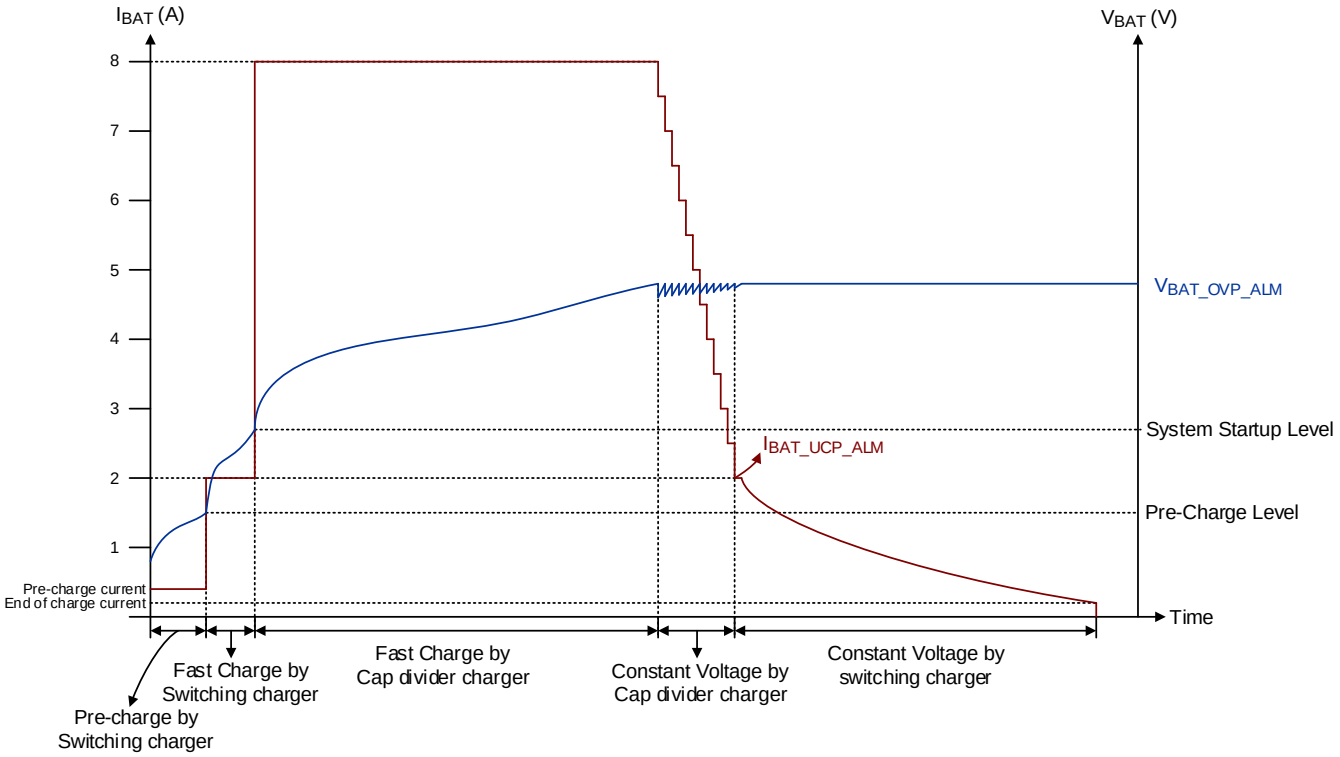


Figure 3. Charge Profile using Switching Charger and Cap Divider Charger

While the RT9756A is charging, the host needs to communicate with smart wall adapter to control the charging current provided by the RT9756A. The communication flow between smart wall adapter and charge system is shown in Figure 4. In order to prevent abnormal events when charging, the RT9756A is established with many adjustable protections and alarm functions. All alarms and protections are activated in specific operation condition that are shown in Table 2 and Table 4, respectively.

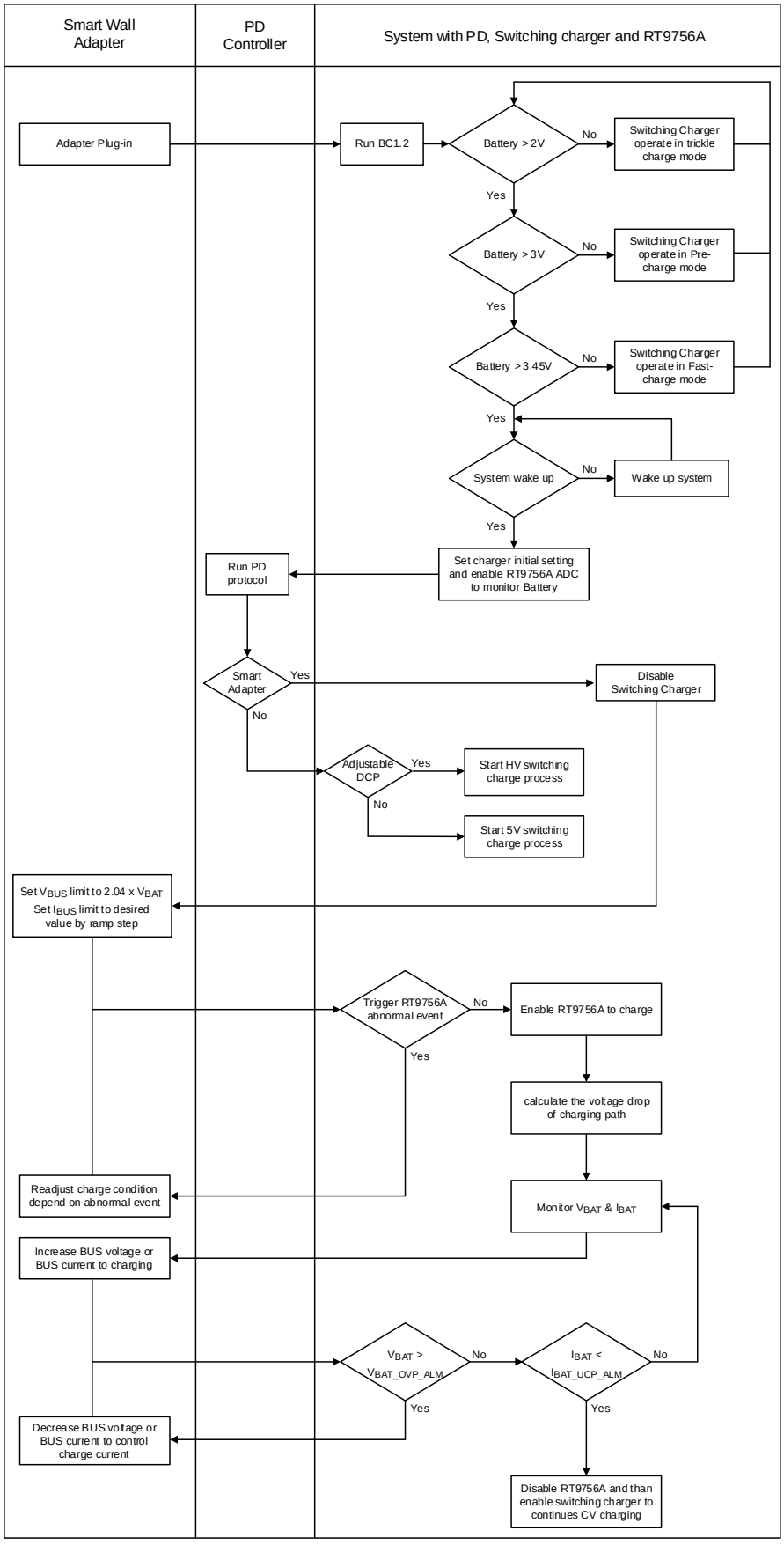


Figure 4. System Control Flow Chart

Device Power-Up

The device is powered by VDDA and the VDDA voltage can be measured through the REGN pin. When V_{DDA} voltage is higher than V_{DDA_UVLO} threshold, the device will start working. The VDDA voltage can be powered by VAC or VBUS or VOUT and that is dominated by the higher voltage level.

Once the RT9756A is powered, the device will activate the address detection mechanism to assign the slave address of device. The slave address of device is determined by the state of the SRN_ADDR pin after power-on. Depending on whether the SRN_ADDR pin is short to ground or floating, the slave address is 0x6F or 0x6E. After address detection is finished, the host can communicate with the RT9756A by I^2C serial interface. Furthermore, the reaction time during V_{DDA} > V_{DDA_UVLO} to I^2C release (t_{VDDA_START}) is around 400μsec.

The RT9756A includes a watchdog timer that is enabled by default. If the device is not read or written before watchdog timer timeout, the ADC_EN and CHG_EN will be set to default value. The register table shows which registers are reset by watchdog. Moreover, the watchdog timeout flag and $\overline{INT}$ pulse will be triggered to inform the host.

If the V_{OUT} is not higher than V_{OUT_INSERT} rising threshold, the charge cannot be enabled. Once V_{OUT} exceeds V_{OUT_INSERT} rising threshold, the minimum allowable V_{OUT} for enable charge is V_{OUT_INSERT} falling threshold. Before charge enable, the RT9756A can report ADC information while the ADC is enabled. After charge enable, the RT9756A reports ADC information no matter whether the ADC is enabled or not.

In order to reduce quiescent current, most of sensing circuit inside the RT9756A will be turned off after address detection is finished and ADC_EN and CHG_EN are disabled for 500ms. In other words, part of protections and insert function are still activated before disabling device sensing circuit. Figure 5 shows the device power on flow with protections and insert function activation list in each state. The VAC_OVP, VBAT_OVP, VOUT_OVP, VBUS_OVP, TDIE_OTP, TS_OTP, VBUS_HIGH_ERR, VBUS_ LOW_ERR, VOUT_INSERT, VBUS_INSERT and VAC_INSERT function are still active before sensing circuits are turned off. When the device disables sensing circuit, all of protections and INSERT function are disabled except VAC_INSERT, VAC_OVP and VBUS_OVP.

8-Channel Analog to Digital Converter

The RT9756A integrates 8-Cannel ADC conversion for users to monitor input and output status of the device. The ADC function is allowed to operate if V_{DDA} > $V_{DDA\_UVLO\_TH}$. Once V_{DDA} exceeds $V_{DDA\_UVLO\_TH}$ rising threshold, the RT9756A will reset ADC_EN to disable if V_{DDA} < $V_{DDA\_UVLO\_TH}$. The ADC function can operate in continuous mode or 1-shot mode. Users can enable ADC function and select conversion mode via I^2C serial interface control (0x0011). In continuous mode, the ADC function will convert all ADC channel and report ADC data to related registers continuously. In 1-shot mode, ADC function will reset ADC_EN bit to 0 after converting each ADC channel. Each ADC channel can be enabled or disabled. The device uses ADC conversion data to detect all alarm function, TS_OTP, VBUS_LOW_ERR and VBUS_HIGH_ERR. Due to this feature, the ADC function will be forced to convert each ADC channel with continuous mode and ADC cannot be controlled via register after charging. Figure 6 is ADC function operation flow chart; Users can follow the flow chart to control ADC function. While reading the data of registers, high byte has to be read firstly, and then the following is low byte. Moreover, high byte and low byte have to be read with I^2C multi-byte reading method in one transmission, which is terminated with one STOP condition.

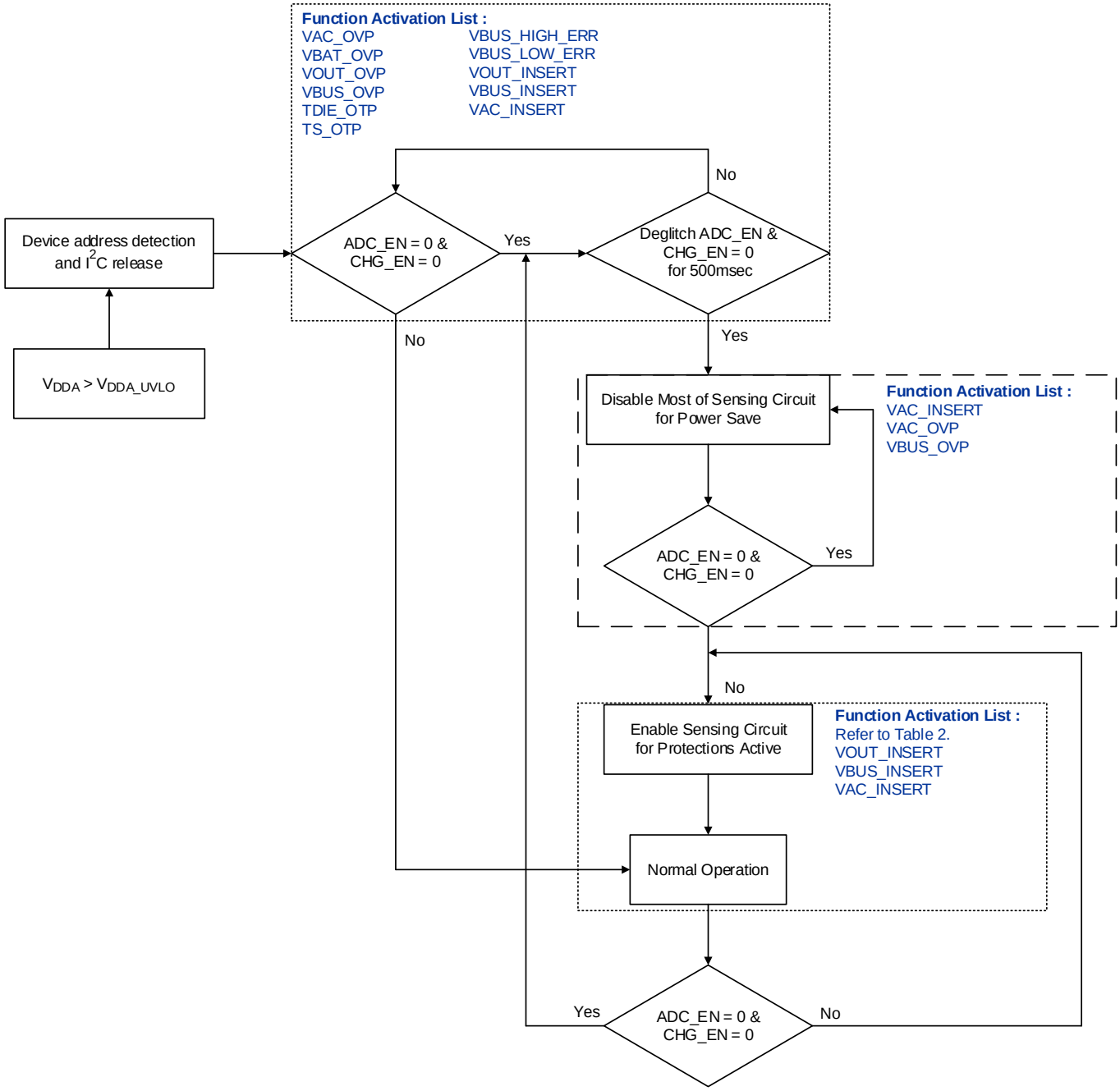


Figure 5. Device Power-On Flow with Protections and Insert Function Activation List

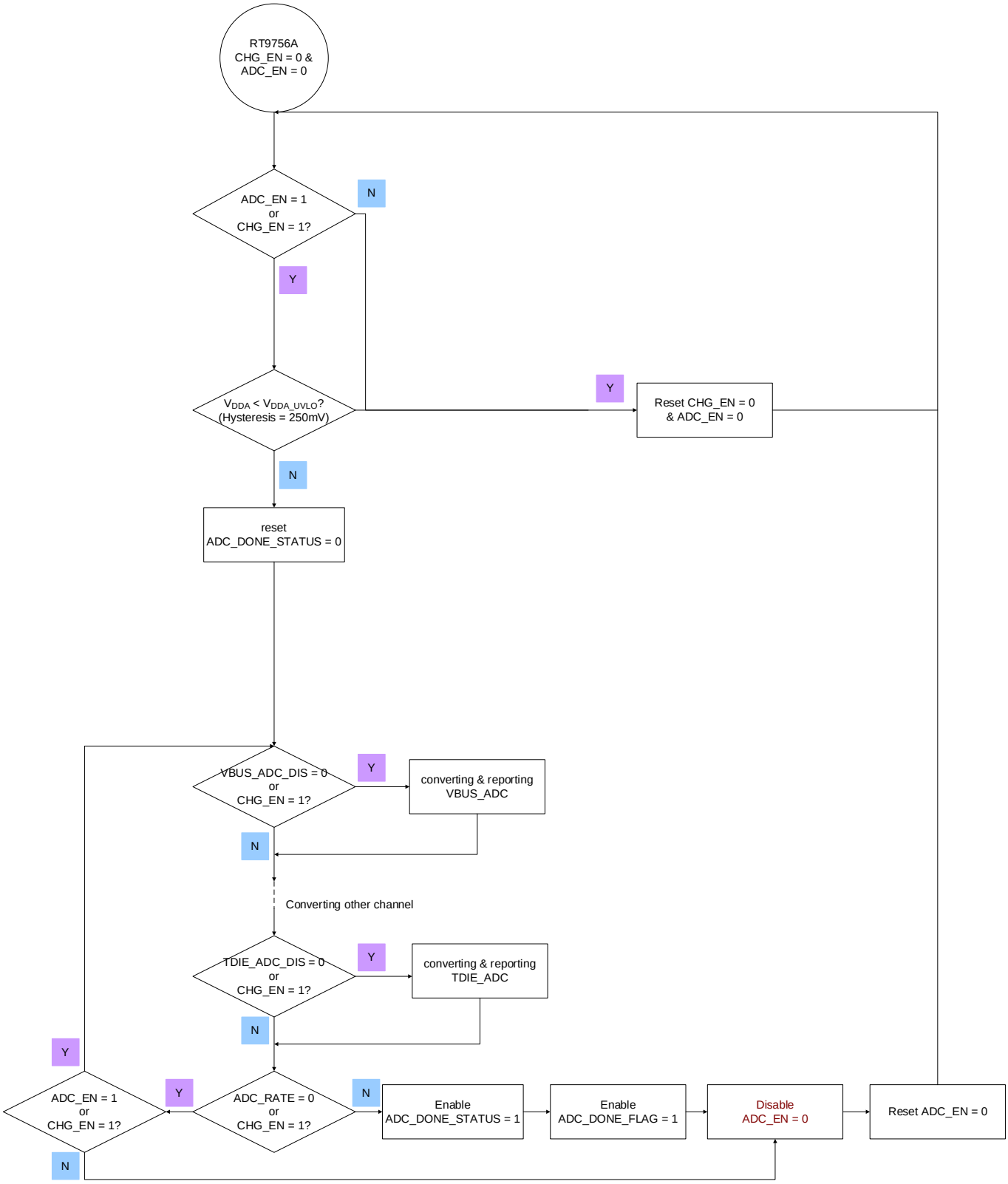


Figure 6. ADC Function Operation Flow Chart

Protection Feature

The RT9756A integrates 14 protections to protect device charging in unexpected condition. All protection activations are based on CHG_EN and ADC_EN bit except VAC_OVP and VBUS_OVP. Users need to set CHG_EN or ADC_EN bit to 1 to enable related protection. Each protection functions can be disabled by enable bits. Table 2 shows the enable condition and protect method for each protection.

Table 2. Protection Trigger Condition and Behavior

Protection Function	Enable Condition	Threshold Refer to Electrical Spec.	Deglitch Time	Protection Method	Reset Method
VAC_OVP	V_{AC} > V_{AC_INSERT} & OVPMOS_DIS = 0	V_{AC} ≥ 12V (Programmable)	NA	Turn off OVPGATE and Reset CHG_EN = 0	V_{AC} lower than hysteresis 500mV
VBUS_OVP	V_{DDA} > V_{DDA_UVLO}	V_{BUS} ≥ 8.9V in DIV2 mode V_{BUS} ≥ 4.5V in DIV2 mode (Programmable)	NA	Reset CHG_EN = 0	V_{BUS} < OVP level
VBAT_OVP	CHG_EN = 1 or ADC_EN = 1	V_{BAT} ≥ 4.35V (Programmable)	3μs	Reset CHG_EN = 0	V_{BAT} < OVP level
VOUT_OVP	CHG_EN = 1 or ADC_EN =1	V_{OUT} ≥ 4.9V	3μs	Reset CHG_EN = 0	V_{OUT} < OVP level
IBUS_OCP	CHG_EN = 1	I_{BUS} ≥ 3A (Programmable)	50μs	Reset CHG_EN = 0	NA
IBUS_OCP_H	CHG_EN = 1	I_{BUS} ≥ 6.8A	NA	Reset CHG_EN = 0	NA
IBUS_UCP	CHG_EN = 1	I_{BUS} ≤ 150mA (Programmable)	22μs (Programmable)	Reset CHG_EN = 0	NA
IBAT_OCP	CHG_EN = 1	I_{BAT} ≥ 7.2A (Programmable)	50μs	Reset CHG_EN = 0	NA
TDIE_OTP	CHG_EN = 1 or ADC_EN = 1	T_{DIE} ≥ 150°C	3μs	Reset CHG_EN = 0	T_{DIE} < OTP level
VDR_OVP	CHG_EN = 1	(V_{AC} - V_{BUS}) ≥ 300mV	8μs (Programmable)	Reset CHG_EN = 0	NA
CFLY_DIAG	CHG_EN = 1	R_{CFLY} ≤ 16Ω	NA	Reset CHG_EN = 0	NA
TS_OTP	(CHG_EN = 1 or ADC_EN =1) & DM_ADC_DIS = 0 & DM_TS_CFG = 1	TS pin ≤ 0V (Programmable)	NA	Reset CHG_EN = 0	TS pin > TS_OTP level
VBUS_LOW_ERR	CHG_EN = 1 (before switching) or ADC_EN = 1 (VBUS_ADC and VOUT_ADC must be enabled)	V_{BUS} / V_{OUT} ≤ 2.04	NA	Reset CHG_EN = 0	V_{BUS} / V_{OUT} > 2.04

Protection Function	Enable Condition	Threshold Refer to Electrical Spec.	Deglitch Time	Protection Method	Reset Method
VBUS_HIGH_ERR	CHG_EN = 1 (before switching) or ADC_EN = 1 (VBUS_ADC and VOUT_ADC must be enabled)	V_{BUS} / V_{OUT} ≥ 2.4	NA	Reset CHG_EN = 0	V_{BUS} / V_{OUT} < 2.4

- **VAC Pin Overvoltage Protection (VAC_OVP)**

  The RT9756A integrates VAC_OVP function to monitor adaptor voltage by VAC pin and control external MOSFET by OVPGATE pin. The VAC_OVP function is powered by VAC pin, it will be enabled if V_{AC} voltage is higher than V_{AC_INSERT} and OVPMOS_DIS is set to 0. The device will provide a $V_{OVPGATE}$ voltage to turn on external MOSFET if V_{AC} is higher than V_{AC_INSERT} for a $t_{VAC\_INSERT\_DEG}$ time. If the V_{AC} voltage is higher than V_{AC_OVP} threshold, the device will start to turn off external MOSFET after a $t_{VAC\_OVP\_RE}$ time and it will turn off the external MOSFET within $t_{VAC\_OVP\_OFF}$ time. Figure 7 shows the timing of VAC_OVP function. Users should make sure the adaptor voltage will not be higher than absolute maximum rating of VAC pin and external MOSFET (prevented by external TVS, etc.).

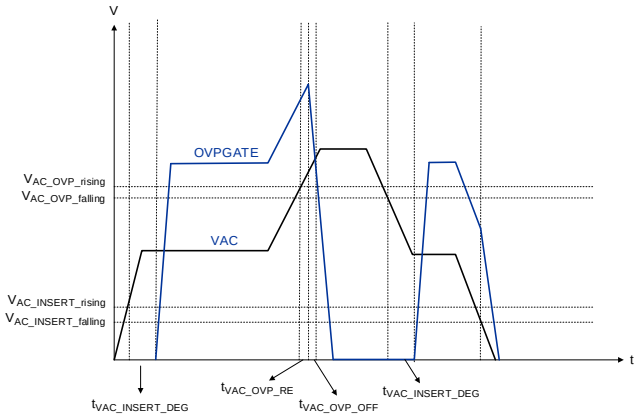


Figure 7. OVPGATE Operation Timing

- **VBUS Charge Voltage Protection (VBUS_HIGH_ERR and VBUS_LOW_ERR)**

  The device integrates VBUS_HIGH_ERR and VBUS_LOW_ERR to prevent users from adjusting wrong VBUS for charge. In no charge condition, if V_{BUS} is higher than $V_{BUS\_HIGH\_ERR}$ threshold or V_{BUS} lower than $V_{BUS\_LOW\_ERR}$ threshold, the device will force CHG_EN bit to disable. Both of VBUS_HIGH_ERR and VBUS_LOW_ERR will be disabled after the device successfully starts to charge. The device diagnoses VBUS_HIGH_ERR and VBUS_LOW_ERR from VBUS ADC and VOUT ADC values. For using these two functions, enabling VBUS ADC and VOUT ADC conversion is necessary.

- **Input and Output Overvoltage Protection (VBUS_OVP, VOUT_OVP, VBAT_OVP)**

  The device has VBUS_OVP, VBAT_OVP and VOUT_OVP functions to detect input and output charge voltage condition. If input and output charge voltage is higher than protection threshold, the device will turn off charger and reset CHG_EN to disable. The VBUS_OVP function monitors VBUS voltage by VBUS pin. The VOUT_OVP function monitors VOUT voltage by VOUT pin. In high charging current application, the system might have large voltage drop between the device and battery pack. For the application, the device integrates VBAT_OVP to monitor differential voltage between BATP and BATN/SRP_SYNCIN. Users should connect a 100Ω resistor with BATP to battery pack to achieve remote sense for the device. Users can adjust the protection level of VBUS_OVP and VBAT_OVP.

- **Input and Output Overcurrent Protection (IBUS_OCP, IBUS_OCP_H, IBAT_OCP)**

  The IBUS_OCP and IBUS_OCP_H functions monitor input current via Q0. If CHG_EN bit is enabled, the Q0 will turn on and IBUS_OCP will start detecting input current. If the I_{BUS} is larger than I_{BUS_OCP} threshold, the device stops charging and resets CHG_EN bit to disable. If the I_{BUS} rises over $I_{BUS\_OCP\_H}$ level fast, the device stops charging immediately after IBUS_OCP_H reaction Time and reset CHG_EN bit to disable. The IBAT_OCP function detects battery current via BATN/SRP_SYNCIN and SRN_ADDR pin. Users should connect a 2mΩ resistor in series with battery pack. The SRN_ADDR and BATN/SRP_SYNCIN should connect on the resistor in parallel. The internal protector will convert the differential voltage of BATN/SRP_SYNCIN and SRN_ADDR to current value. The ratio between the differential voltage and current value can be determined by register setting. If the current value is larger than I_{BAT_OCP} threshold, the device will stop charging and reset CHG_EN to disable. Users can adjust the IBUS_OCP and IBAT_OCP threshold via register setting.

- **Input Undercurrent Protection (IBUS_UCP)**

  The device integrates IBUS_UCP function to prevent reverse current from battery to VBUS. The IBUS_UCP detects input current by Q0. Figure 8 shows the flow chart of IBUS_UCP, the device enables IBUS_UCP_RISE threshold and counting timer after start charging. Once I_{BUS} is larger than $I_{BUS\_UCP\_RISE}$ threshold, the device will stop counting timer and enable IBUS_UCP_FALL threshold. If the I_{BUS} is smaller than $I_{BUS\_UCP\_RISE}$ and the timer is already longer than $I_{BUS\_UCP\_TIMEOUT}$, the device will enable IBUS_UCP_FALL threshold. After the device enables IBUS_UCP_FALL threshold, if the I_{BUS} is smaller than $I_{BUS\_UCP\_FALL}$ threshold, the device will stop charging and reset CHG_EN to disable. Figure 9 shows IBUS_UCP behavior in different application.

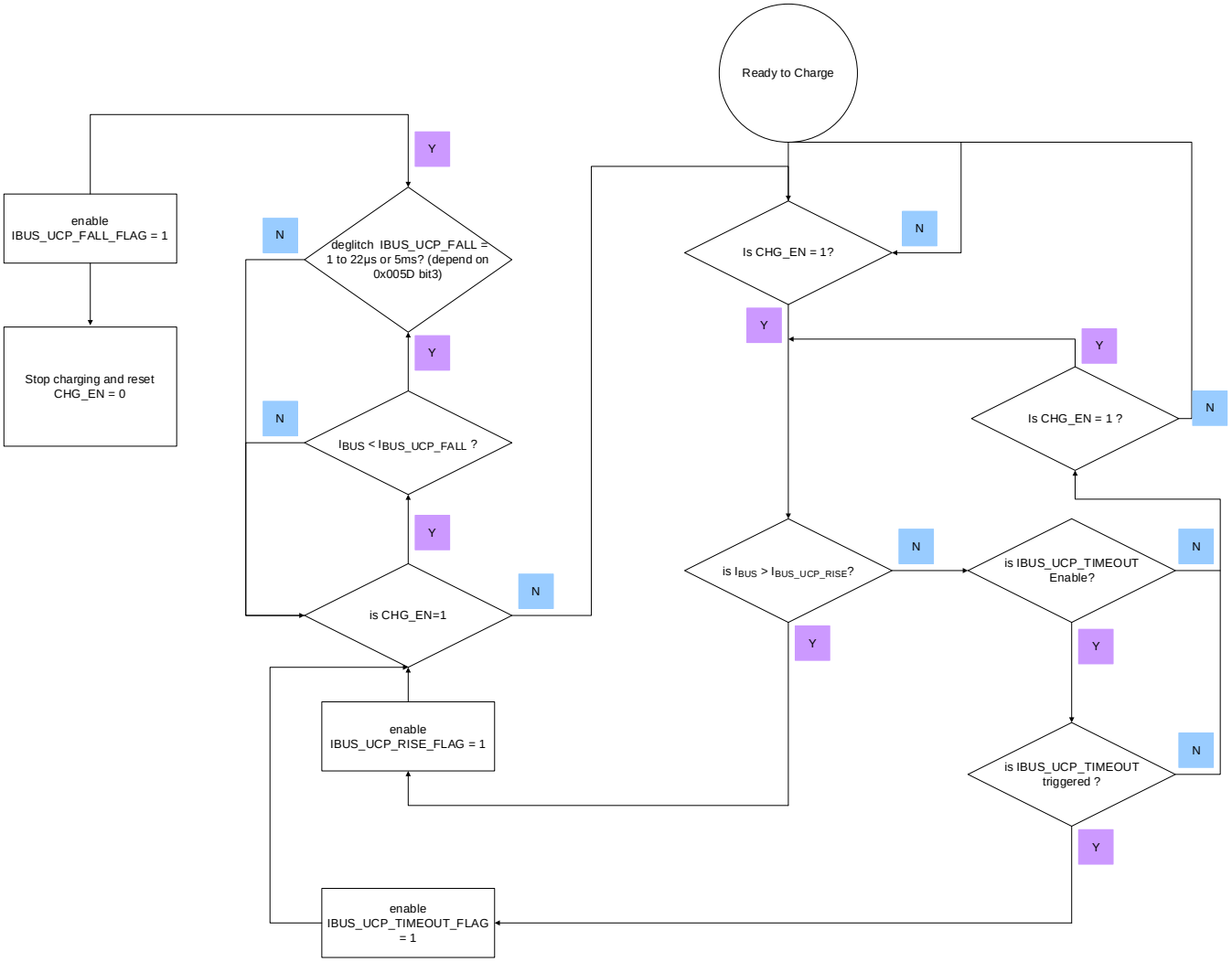


Figure 8. Flow Chart of IBUS_UCP Function

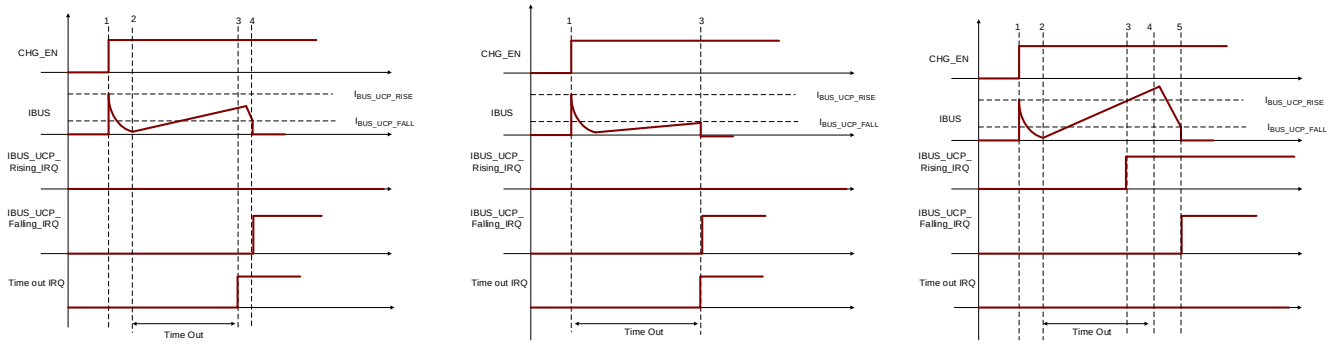


Figure 9. IBUS_UCP Behavior in Different Application

- **Device Thermal Shutdown (TDIE_OTP)**

  The device integrates TDIE_OTP to prevent system charging in over-temperature condition. The TDIE_OTP function monitors the die temperature of the device. If the die temperature is higher than T_{DIE_OTP} threshold, the device will stop charging and reset CHG_EN bit to disable.

- **Flying Capacitor Diagnose (CFLY_DIAG)**

  The device integrates CFLY_DIAG function to diagnose the health of flying capacitors. After CHG_EN is enabled, the device starts soft-start process in t_{SOFT_START}. In the soft-start process, the CFLY_DIAG function will diagnose the resistance between CFL and CFH for each phase. If the resistance is smaller than R_{CFLY_DIAG}, the device will stop soft-start process and reset CHG_EN to disable. If the device succeeds to start charging after soft-start process, the CFLY_DIAG function will stop activating. If the CFLY is short after soft-start, the device can be protected by other protections (e.g., IBUS_OCP, VBAT_OVP, VOUT_OVP, CON_OCP, etc.).

- **Dropout Voltage Protection (VDR_OVP)**

  The large voltage drop on external MOSFET might cause high power loss and a lot of heat in the system. In order to prevent the situation, the device integrates VDR_OVP function to monitor the voltage drop between VAC and VBUS pin. If the voltage drop is higher than V_{DR_OVP} threshold, the device will stop charging and reset CHG_EN to disable.

- **TS Over-Temperature Protection (TS_OTP)**

  The device integrates temperature sense (TS) function to diagnose the external temperature with NTC thermistor. The voltage on NTC thermistor varies with different temperature. Figure 10 shows the DM_TS pin connection for the TS function. The device diagnoses TS_OTP from the DM_TS pin ADC value if DM_TS_CFG(0x005F[6]) is set to 1. If the external sensing voltage is lower than TS_OTP threshold, the device will stop charging and reset CHG_EN bit to disable. The temperature information is derived from the DM_TS pin ADC value. For using this function, enabling DM ADC conversion is necessary.

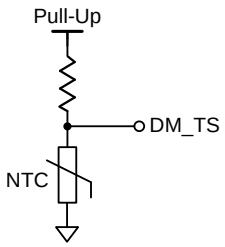


Figure 10. TS Function Connection

Regulation Feature

The device has VBAT_REG and IBAT_REG regulation functions to regulate instant current change and voltage change for the battery. Users can set the regulation threshold by register setting.

The VBAT_REG function monitors differential voltage between BATP and BATN/SRP_SYNCIN pin. If the differential voltage is higher than V_{BAT_REG} threshold, the device will control OVPGATE voltage to regulate charge current. IBAT_REG function converts the differential voltage between SRN_ADDR and BATN/SRP_SYNCIN to current value. If the current value is higher than I_{BAT_REG} threshold, the device will control OVPGATE voltage to regulate charge current. If the regulation functions are triggered and persist for $t_{REG\_TIMEOUT}$, the device will stop charging and reset CHG_EN to disable. When regulation functions are triggered, system should adjust charging condition to prevent the device from triggering the $t_{REG\_TIMEOUT}$ and VDR_OVP.

Alarm Feature

The device integrates 9 alarm functions for system to monitor the charge condition. The alarm functions use the ADC conversion data to monitor the charge condition. Table 3 shows the relationship between alarm functions and ADC channels, users should make sure the ADC channel is enabled when using related alarm functions. If the alarm function is triggered, the device will send an interrupt to alarm system but charger will not stop charging. Table 4 shows the enable condition for each alarm.

Table 3. Alarm Function with Related ADC Channel

Alarm Function	Related ADC Channel Need Enabled	Sense Node
VBAT_OVP_ALM	VBAT_ADC	BATP and BATN/SRP_SYNCIN pin
IBAT_OCP_ALM	IBAT_ADC	BATN/SRP_SYNCIN and SRN_ADDR pin
IBAT_UCP_ALM	IBAT_ADC	BATN/SRP_SYNCIN and SRN_ADDR pin
VBUS_OVP_ALM	VBUS_ADC	VBUS pin
IBUS_OCP_ALM	IBUS_ADC	Q0
IBUS_UCP_ALM	IBUS_ADC	Q0
TDIE_OTP_ALM	TDIE_ADC	DIE temperature
DP_OV_ALM	DP_ADC	DP pin
DM_OV_ALM	DM_ADC	DM pin

Table 4. Alarm Function Activation List

Alarm Function	Enable Condition
VBUS_OVP_ALM	CHG_EN = 1 or ADC_EN =1
VBAT_OVP_ALM	CHG_EN = 1 or ADC_EN =1
IBUS_OCP_ALM	CHG_EN = 1
IBUS_UCP_ALM	CHG_EN = 1
IBAT_OCP_ALM	CHG_EN = 1
IBAT_UCP_ALM	CHG_EN = 1
TDIE_OTP_ALM	CHG_EN = 1 or ADC_EN =1
DP_OV_ALM	ADC_EN =1 & DP_ADC_DIS=0
DM_OV_ALM	ADC_EN =1 & DM_ADC_DIS=0

External MOSFET Control by OVPGATE

The RT9756A has one OVPGATE pin to control the external MOSFET. The external MOSFET control can support both the single or the back-to-back external N-channel MOSFET. The external MOSFET can be controlled on or off by setting register OVPMOS_DIS. If OVPMOS_DIS is set to 0, the OVPGATE pin will drive external MOSFET to turn on when the VAC voltage is higher than V_{AC_INSERT} threshold or the VBUS voltage is higher than V_{BUS_INSERT} threshold for a $t_{VAC\_INSERT\_DEG}$ time. The OVPGATE pin will drive external MOSFET to turn off if the V_{AC} voltage is lower than V_{AC_INSERT} threshold and the V_{BUS} voltage is lower than V_{BUS_INSERT} threshold. If the VAC OVP event is present, the external MOSFET will be also turned off. The information is detailed in VAC_OVP function description section. If OVPMOS_DIS is set to 1, the OVPGATE pin will force external MOSFET to turn off.

The voltage between OVPGATE to VBUS can be set to 10V or 4.8V by OVPGATE(0x0004[0]). If the OVPGATE voltage level has to be changed, OVGATE and charger must be disable(0x0004[6] = 1 and 0x0000[6] = 0) first, and then set the OVPGATE voltage level. After over 2ms, the OVPGATE can be enabled again. Figure 11 shows the flow of changing OVPGATE setting. OVPGATE register control bit cannot be set if OVPMOS_DIS = 0 or CHG_EN = 1.

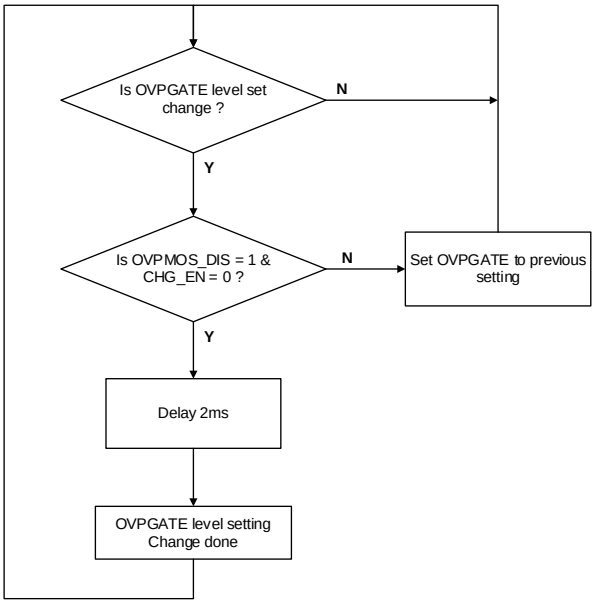


Figure 11. Flow Chart of Changing OVPGATE Setting

BC1.2 General Description

The BC1.2 detection is through USB2.0 D+ and D- lines upon connection. There are three charging ports defined in the BC1.2 spec: Dedicated Charging Port (DCP), Charging Downstream Port (CDP) and Standard Downstream Port (SDP). The detection results are reported in USB_STATUS (0x0046[7:5]). When the adapter is plugged in, the device can start BC1.2 detection if BC12_EN = 1 (0x0044[7] = 1). Data Contact Detect timeout can be set by DCD_TIMEOUT_SET (0x0044[6:5]). The RT9756A supports both portable device role (sink role) and downstream port or charging downstream port (source role). When the device is source role, set HOST_MODE (0x0044[3:2]) to choose the charging port type. BC12_EN (0x0044[7]), HOST_MODE (0x0044[3:2]) and other protocol function cannot be enabled in the same time. To change the charging port type, HOST_MODE (0x0044[3:2]) must be set to 00 first.

DP/DM Output Control Mode

DP/DM output control mode is enabled by SET_DPDM_EN(0x0048[7]). The output is controlled by programmed SET_DP (0x0048[6:4]) and SET_DM (0x0048[3:1]). The device will ignore BC1.2 detection when SET_DPDM_EN = 1.

I²C Level Selection

The RT9756A can support VDD = 1.2V or 1.8V of I²C. When EN_I2C_LEVEL_DETECTION (0x005E[7]) is enable, I²C level can change from 1.2V to 1.8V if pull-up voltage of SDA pin is higher than $V_{TH\_I2C\_level}$, and I2C_level (0x005E[6]) will be 0. Because I²C level detection function is not automatically disabled, users should disable this function after the RT9756A wakes up and VDD of I²C is ready. If users want to set I2C_level (0x005E[6]), EN_I2C_LEVEL_DETECTION (0x005E[7]) must be disable first. I²C level detection function would not change I²C level from 1.8V to 1.2V even if SDA voltage is lower than $V_{TH\_I2C\_level}$. If users want to charge I²C level from 1.8V to 1.2V, disabled EN_I2C_LEVEL_DETECTION (0x005E[7]) first, then set I2C_level (0x005E[6]) = 1.

Interrupt (INT), STAT, FLAG AND MASK

The $\overline{INT}$ pin is an open drain structure; users should connect a supply voltage via a current source or pull-up resistors on the pin. When the device triggers an event, the $\overline{INT}$ pin will pull-low for $t_{INT\_PULL\_LOW}$ to notify host. The register map shows all state, flag and control bit of the device.

When the device triggers the event with FLAG, it will send an INT signal to host and set the FLAG bit to 1. The FLAG bit can be cleared after read. The device will not send another INT signal until the FLAG is cleared and a new event occurs again. The MASK bit can disable INT pin to send a signal to host. The STAT and FLAG bit are still updated even though the MASK bit is set to 1.

The STAT bits show current statue of the device and are updated as the status change. All of STAT bits will not send INT signal to system when the STAT bit is triggered except SWITCHING_STAT.

Spread Spectrum

The device integrates spread spectrum function for users to optimize the EMI influence on system design. The device switching frequency is decided by register 0x0001[7:4]. The spectral density will concentrate on the switching frequency. Users can enable the spread spectrum function by set 0x0001[3:2] register. After the spread spectrum function is enabled, the device will modulate the switching frequency for ±10% to reduce the spectral density.

Parallel Application

For high capacity battery charging application, it is available to use two RT9756A in parallel architecture. The advantages of using parallel architecture are reducing cable losses, improve efficiency of charge system and cut down charging period. The high power solution that uses two RT9756A are shown in Figure 12.

In order to avoid unstable ripple issue while charging with parallel architecture, the RT9756A is established with synchronization function at the DP_SYNCOUT pin and BATN/SRP_SYNCIN pin. The DP_SYNCOUT pin and BATN/SRP_SYNCIN pin are multi-function pins that depends on different configuration. The slave address is configured by SRN_ADDR pin while device powers up, and the configuration mode is set by DP_SYNCOUT_CFG (0x005F[7]) or BATN_SRP_SYNCIN_CFG (0x005F[5]). Table 5 shows the configuration mode setting. When RT9756A is configured to master mode (RT9756A_M), the DP_SYNCOUT pin provides synchronization pulses with frequency equal to twice switching frequency and 50% duty cycle, so the DP and DM pin cannot implement any protocol function. When RT9756A is configured to slave mode (RT9756A_S), the BATN/SRP_SYNCIN pin is used to receive pulses for synchronization, so the VBAT and IBAT sense functions are disabled. For using the synchronization function, the DP_SYNCOUT pin of master device and BATN/SRP_SYNCIN pin of slave device should be connected to each other. BATN_SRP_SYNCIN_CFG cannot set to 1 when slave address is 0x6F, and DP_SYNCOUT_CFG cannot set to 1 when slave address is 0x6E.

In DIV2 mode, all of phase angle in the device need to be defined correctly for optimize output ripple and charging efficiency, especially parallel application. The A phase between master and slave device should be shifted 90 degrees, the A and B phase in the same device should be shifted 180 degrees. It is strongly prohibited to change PHASE_A_ANGLE (0x0002[3:2]) and PHASE_B_ANGLE (0x0002[1:0]) during charging.

In parallel application, only master device's OVP MOSFET is used. Furthermore, the OVPGATE function should be turned off in slave device and the OVPGATE pin should be left floating. Moreover, only slave device's DP and DM pin can be used. To enable DPDM protocol function, VAC_INSERT_PROTOCOL_DIS should be set to 1 because all protocol function is restricted by VAC_INSERT_STAT = 1.

If parallel architecture is used, the start-up sequence should be compiled with the rules below. The RT9756A_S should be enabled before host enables the RT9756A_M in order to achieve parallel application. The RT9756A_S will not switch until the BATN/SRP_SYNCIN pin receives synchronization pulses provided by the RT9756A_M. The communication flow between smart wall adapter and parallel charge system is shown in Figure 13.

Table 5. Configuration Mode Setting Description

Slave Address	Register	Configuration
0x6F	DP_SYNCOUT_CFG = 0	Standalone
0x6F	DP_SYNCOUT_CFG = 1	Master
0x6E	BATN_SRP_SYNCIN_CFG = 0	Standalone
0x6E	BATN_SRP_SYNCIN_CFG = 1	Slave

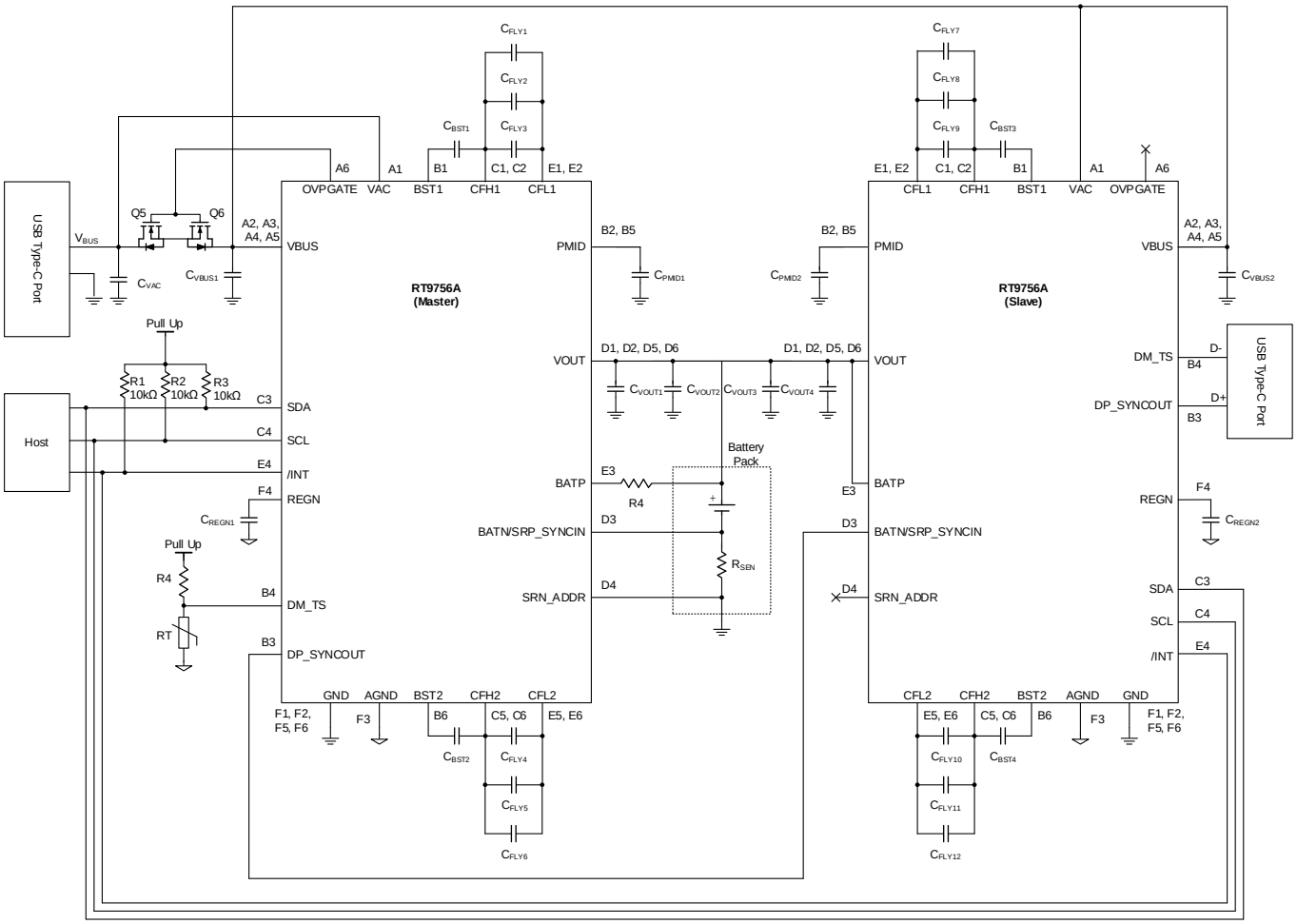


Figure 12. Parallel Application Circuit

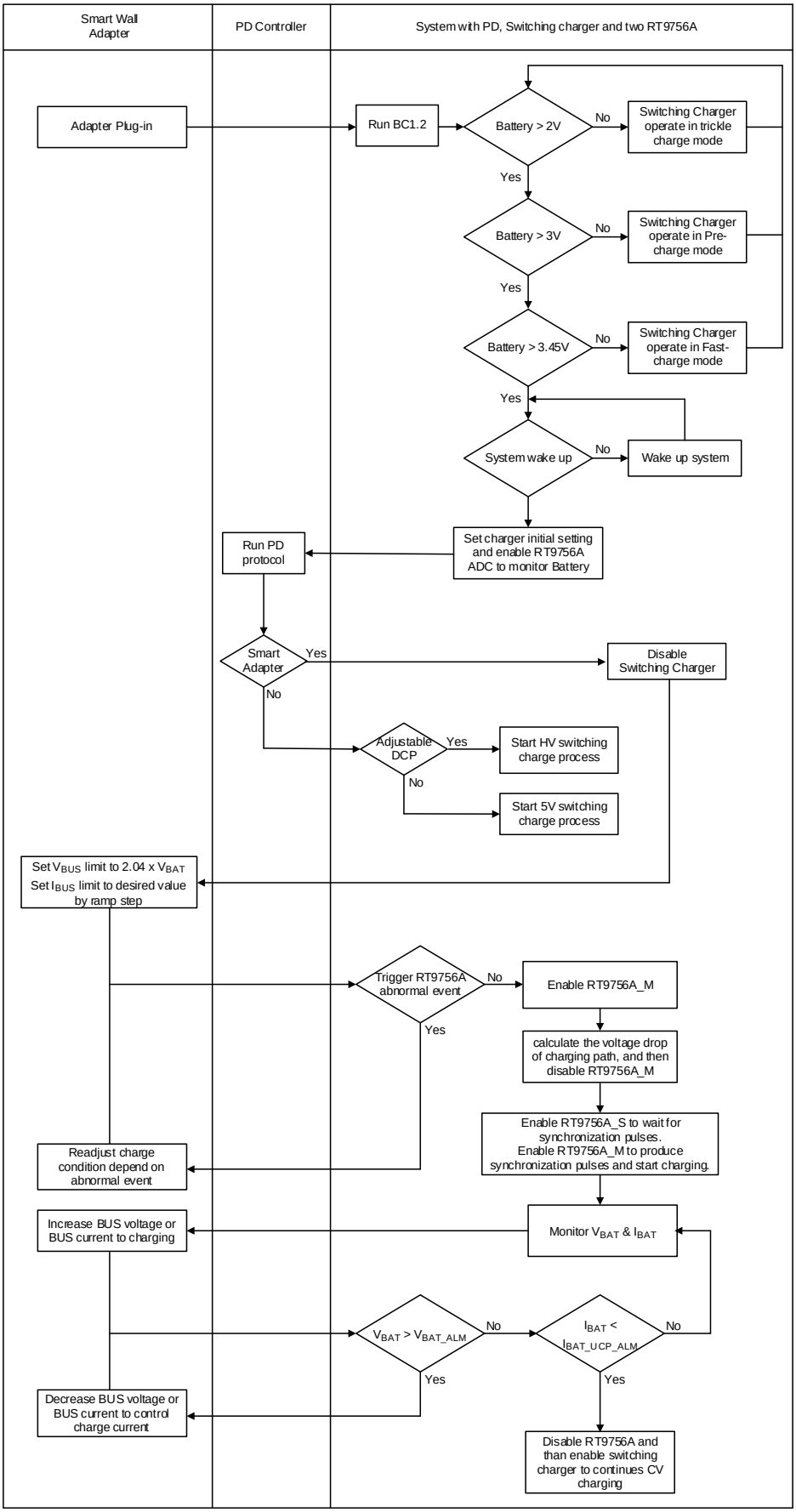


Figure 13. System Control Flow Chart with Parallel Charge System

I²C Serial Interface

The RT9756A integrates I²C interface for host to program charging parameter and monitor device status. The interface requires a serial clock line (SCL) and a serial data line (SDA). The host should initiate a data transfer on the bus and generates the clock signals to permit that transfer. The device operates with address 0x6F or 0x6E to receive control input from the host. The SCL and SDA pin are open drain structures. Users should connect a supply voltage via a current source or pull-up resistors on SCL and SDA. Figure 14 shows the I²C waveform information, the data line must be stable during the high period of SCL line. The high or low state of SDA can only change when SCL line is low.

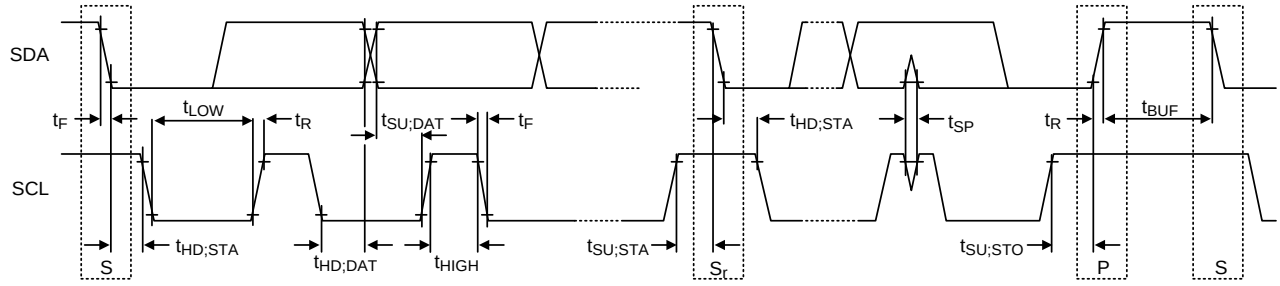


Figure 14. I²C Waveform Information

The RT9756A operates as an I²C slave device with address 0x6F or 0x6E (depends on SRN_ADDR pin). Every byte on SDA line must be 8-bit long. The register address size is two byte. Send the high byte of the register address first and then the low byte of the register address. Figure 15 shows the byte format. All of transactions begin with a START pattern and can be terminated with a STOP pattern. After START, the master should send a slave address. The slave address is 7-bit long followed by the eighth bit as a data direction bit (R/W). The direction bit setting to 0 indicates a transmission and 1 indicates a request for data. The master should take an acknowledge bit after every byte. The master should release SDA line during the acknowledge clock pulse so the slave device can pull low the SDA line to signal the master that the byte was successfully received. The RT9756A supports multi read/write and SCL line can be up to 3.4MHz.

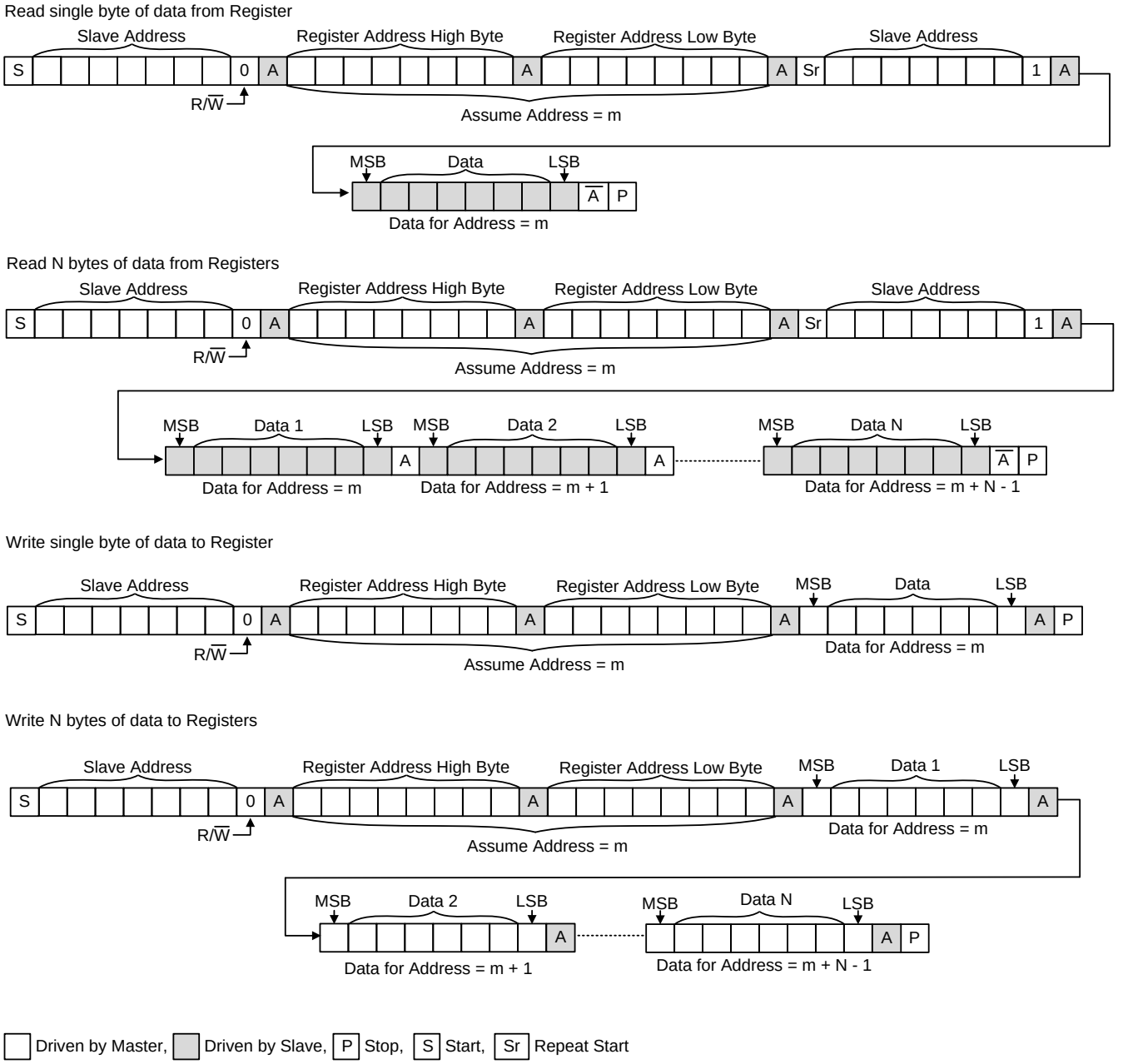


Figure 15. Read and Write Function

Thermal Considerations

The junction temperature should never exceed the absolute maximum junction temperature $T_{J(MAX)}$, listed under Absolute Maximum Ratings, to avoid permanent damage to the device. The maximum allowable power dissipation depends on the thermal resistance of the IC package, the PCB layout, the rate of surrounding airflow, and the difference between the junction and ambient temperatures. The maximum power dissipation can be calculated using the following formula:

$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$

where $T_{J(MAX)}$ is the maximum junction temperature; T_A is the ambient temperature; and θ_{JA} is the junction-to-ambient thermal resistance.

For continuous operation, the maximum operating junction temperature indicated under Recommended Operating Conditions is normally 125°C. The junction-to-ambient thermal resistance, θ_{JA}, is highly package dependent. For a WL-CSP-36B 2.8 x 2.8 (BSC) package, the thermal resistance, θ_{JA}, is 29.26°C/W on a standard JEDEC low effective-thermal-conductivity two-layer test board. The maximum power dissipation at T_A = 25°C can be calculated as below:

$P_{D(MAX)}$ = (125°C - 25°C) / (29.26°C/W) = 3.42W for a WL-CSP-36B 2.8 x 2.8 (BSC) package.

The maximum power dissipation depends on the operating ambient temperature for the fixed $T_{J(MAX)}$ and the thermal resistance, θ_{JA}. The derating curves in Figure 16 allows the designer to inspect the effect of rising ambient temperature on the maximum power dissipation.

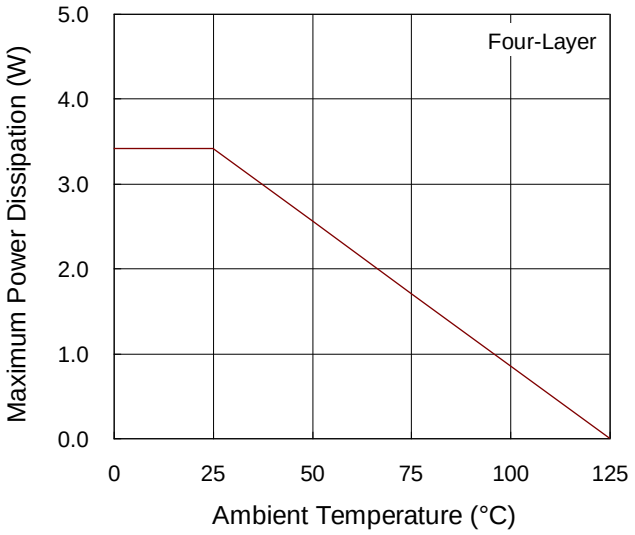


Figure 16. Derating Curve of Maximum Power Dissipation

Layout Considerations

The RT9756A layout guidelines are recommended as below:

- Place low ESR bypass capacitor to GND for PMID/VOUT/VBUS pin. The bypass capacitor needs to be placed as close as possible to the RT9756A.
- The capacitor of REGN/BST1/BST2 should be placed as close as possible to the RT9756A.
- Place flying caps with the RT9756A on same layer. The flying caps should be placed as close as possible to the RT9756A. The path of flying caps should be as small as possible. Two phases' flying caps trace and copper pour should be as symmetrical as possible
- The VBUS and VOUT traces should be as wide as possible to accommodate high charge current.
- Place differential line for VBATP/VBATN and SRP/SRN. Do not route the differential line across power pad especially the flying caps.

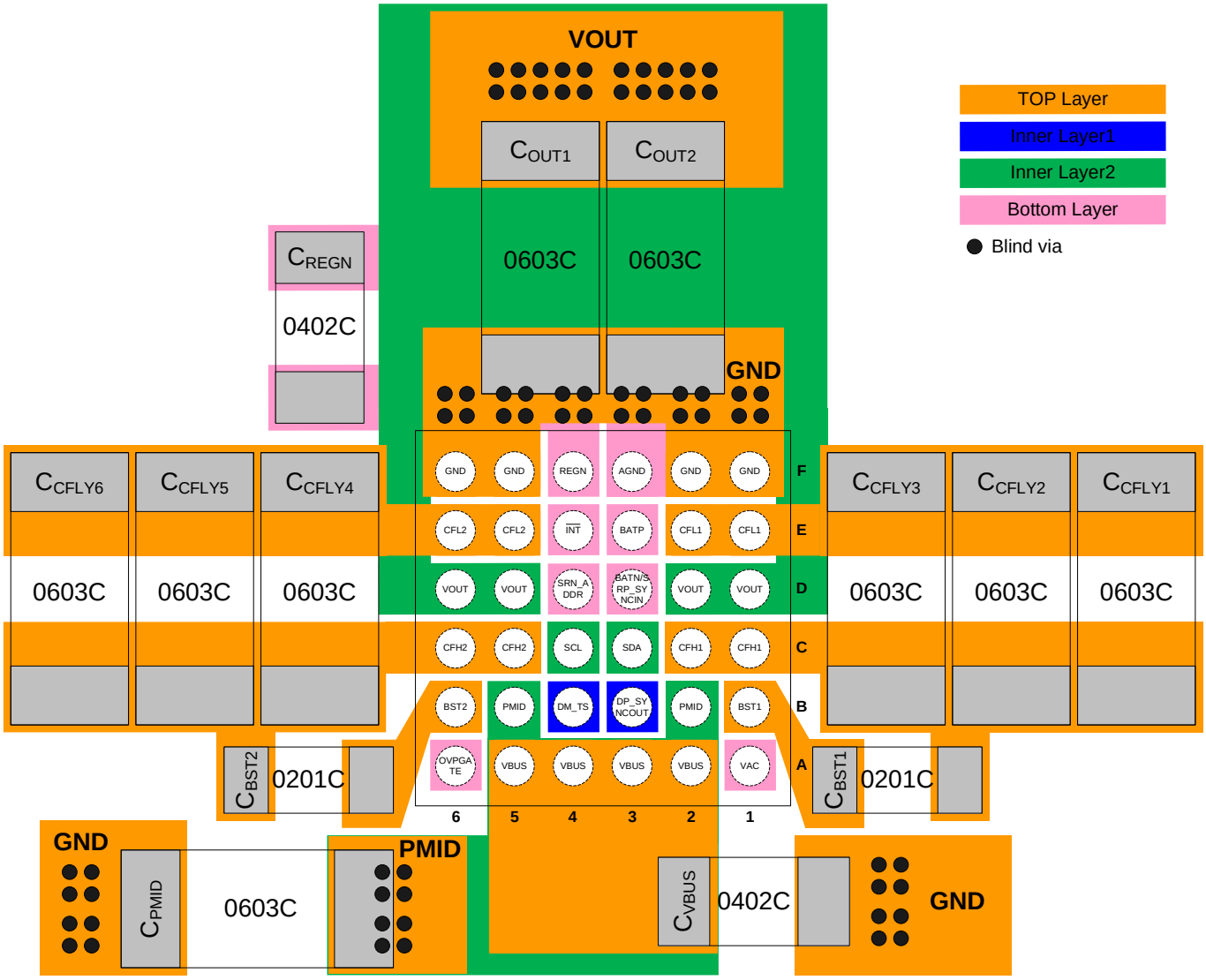
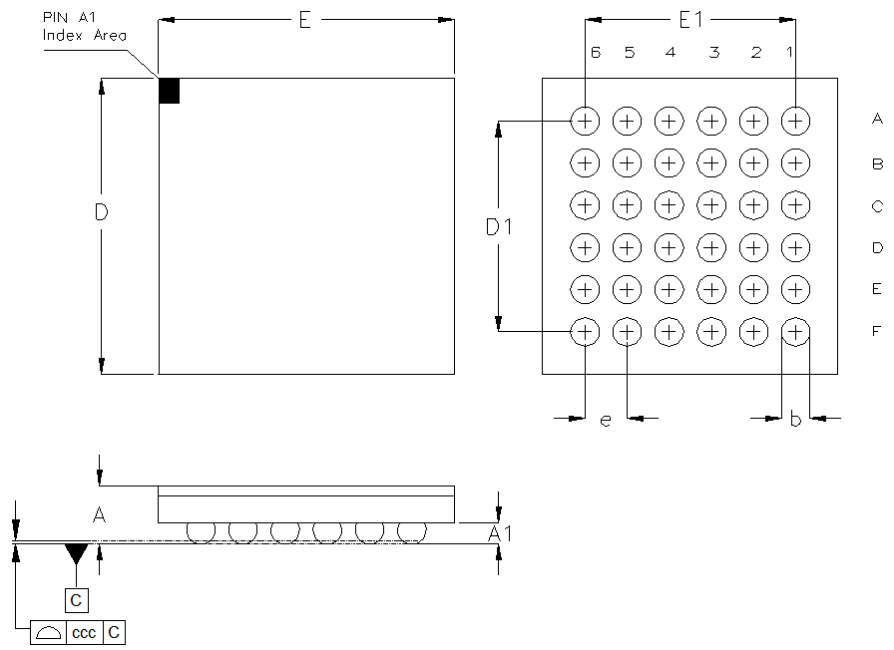


Figure 17. PCB Layout Guide

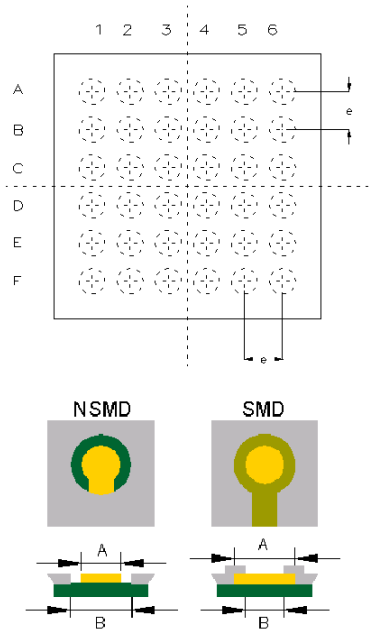
Outline Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.500	0.600	0.020	0.024
A1	0.170	0.230	0.007	0.009
b	0.240	0.300	0.009	0.012
D	2.765	2.835	0.109	0.112
D1	2.000		0.079	
E	2.765	2.835	0.109	0.112
E1	2.000		0.079	
e	0.400		0.016	
ccc	0.020		0.001	

36B WL-CSP 2.8x2.8 Package (BSC)

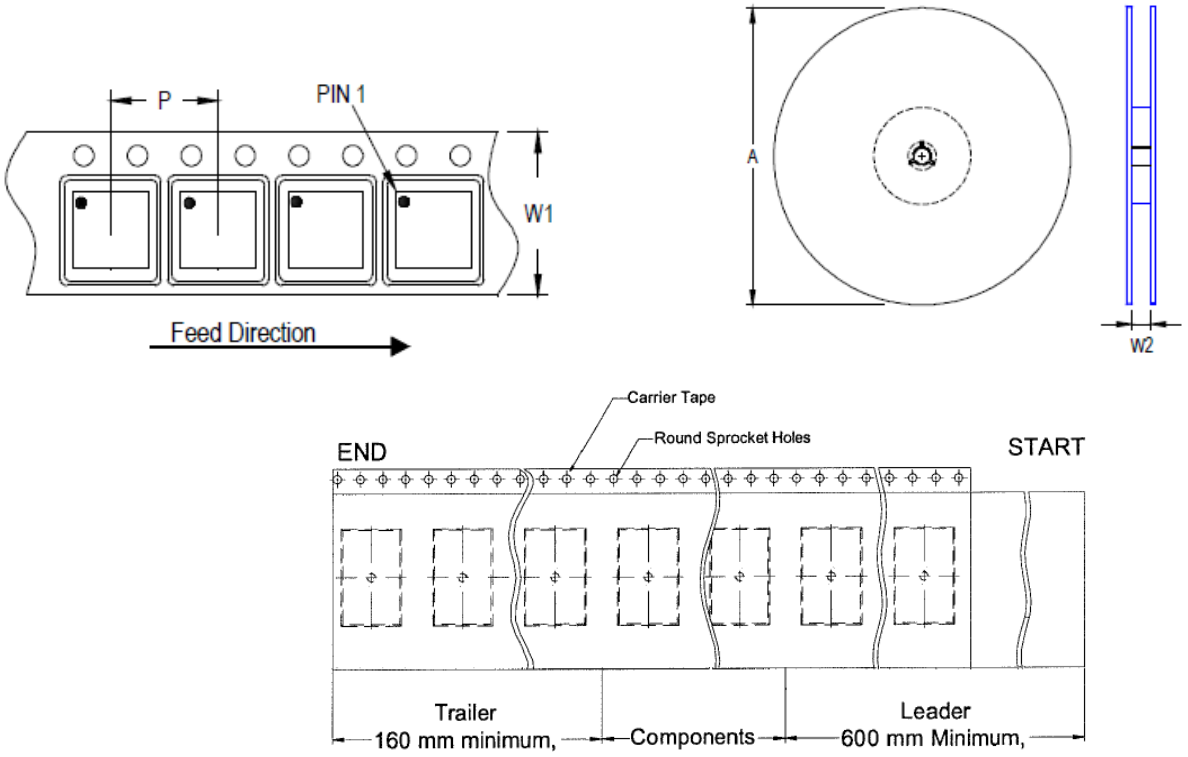
Footprint Information



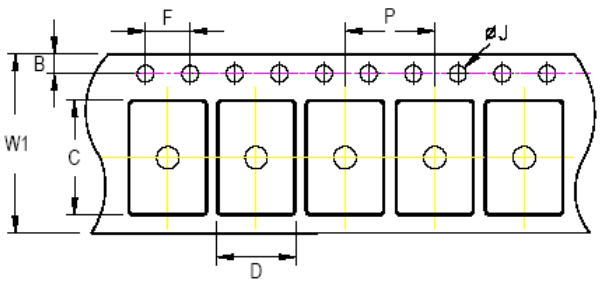
Package	Number of Pin	Type	Footprint Dimension (mm)			Tolerance
			e	A	B	
WL-CSP2.8x2.8-36(BSC)	36	NSMD	0.400	0.240	0.340	±0.025
		SMD		0.270	0.240	

Packing Information

Tape and Reel Data - RT9756AP-A



Package Type	Tape Size (W1) (mm)	Pocket Pitch (P) (mm)	Reel Size (A)		Units per Reel	Trailer (mm)	Leader (mm)	Reel Width (W2) Min./Max. (mm)
			(mm)	(in)				
WL-CSP 2.8x2.8	8	4	180	7	3,000	160	600	8.4/9.9



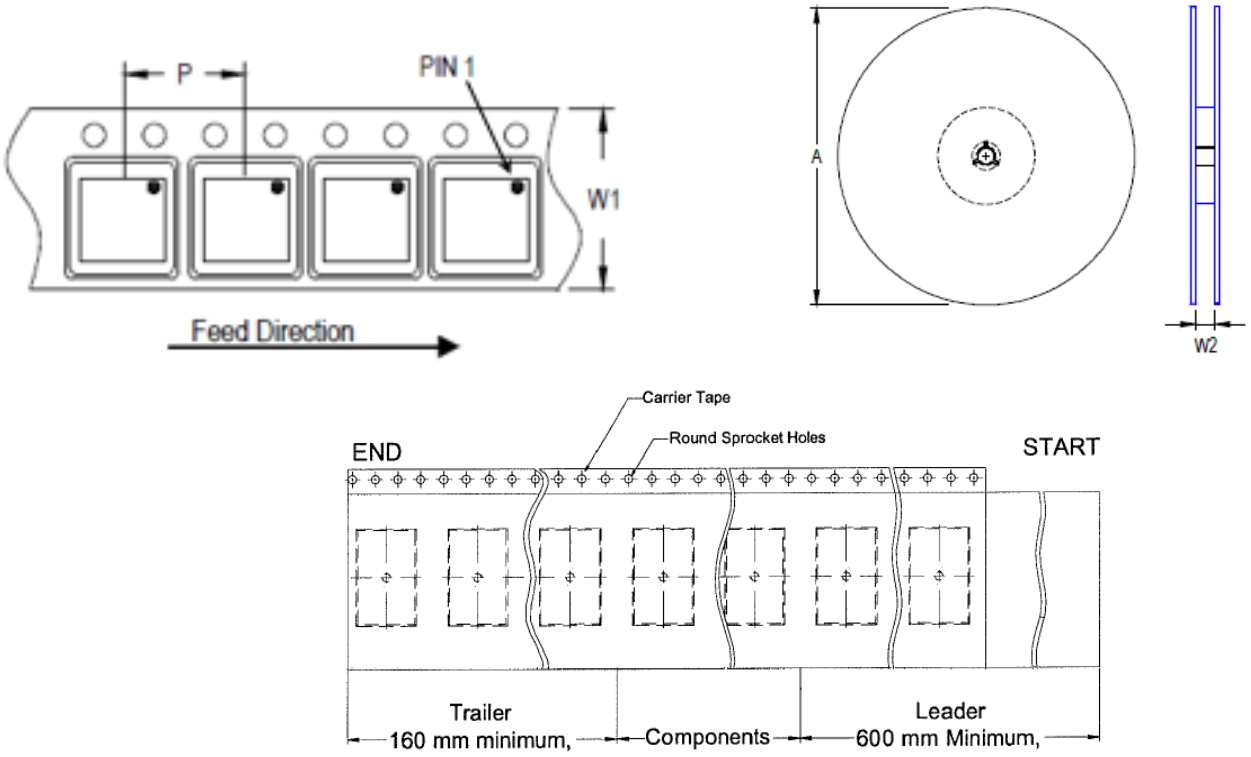
C, D, and K are determined by component size.

The clearance between the components and the cavity is as follows:

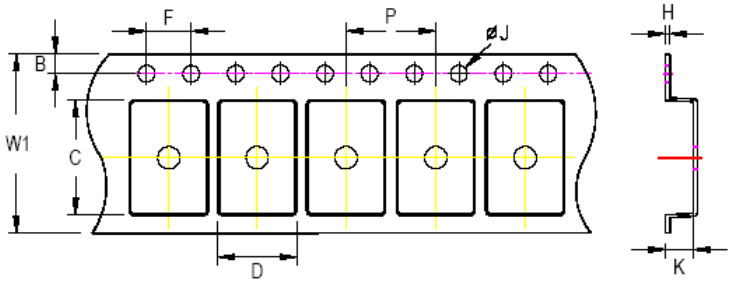
- For 8mm carrier tape: 0.5mm max.

Tape Size	W1	P		B		F		ØJ		H
	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Max.
8mm	8.3mm	3.9mm	4.1mm	1.65mm	1.85mm	3.9mm	4.1mm	1.5mm	1.6mm	0.6mm

Tape and Reel Data - RT9756AP-B



Package Type	Tape Size (W1) (mm)	Pocket Pitch (P) (mm)	Reel Size (A)		Units per Reel	Trailer (mm)	Leader (mm)	Reel Width (W2) Min./Max. (mm)
			(mm)	(in)				
WL-CSP 2.8x2.8	12	8	180	7	1,500	160	600	12.4/14.4



C, D, and K are determined by component size.

The clearance between the components and the cavity is as follows:

- For 12mm carrier tape: 0.5mm max.

Tape Size	W1	P		B		F		ØJ		H
	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Max.
12mm	12.3mm	7.9mm	8.1mm	1.65mm	1.85mm	3.9mm	4.1mm	1.5mm	1.6mm	0.6mm

Tape and Reel Packing - RT9756AP-A

Step	Photo/Description	Step	Photo/Description
1	 Reel 7”	4	 12 inner boxes per outer box
2	 Packing by Anti-Static Bag	5	 Outer box **Carton A**
3	 3 reels per inner box **Box A**	6	

Container / Package	Reel		Box				Carton			
	Size	Units	Item	Size(cm)	Reels	Units	Item	Size(cm)	Boxes	Unit
WL-CSP 2.8x2.8	7”	3,000	Box A	18.3*18.3*8.0	3	9,000	Carton A	38.3*27.2*38.3	12	108,000
			Box E	18.6*18.6*3.5	1	3,000	For Combined or Partial Reel.			

Tape and Reel Packing - RT9756AP-B

Step	Photo/Description	Step	Photo/Description
1	 Reel 7”	4	 3 reels per inner box **Box A**
2	 HIC & Desiccant (1 Unit) inside	5	 12 inner boxes per outer box
3	 Caution label is on backside of Al bag	6	 Outer box **Carton A**

Container / Package	Reel		Box				Carton			
	Size	Units	Item	Size(cm)	Reels	Units	Item	Size(cm)	Boxes	Unit
WL-CSP 2.8x2.8	7”	1,500	Box A	18.3*18.3*8.0	3	4,500	Carton A	38.3*27.2*38.3	12	54,000
			Box E	18.6*18.6*3.5	1	1,500	For Combined or Partial Reel.			

Packing Material Anti-ESD Property

Surface Resistance	Aluminum Bag	Reel	Cover tape	Carrier tape	Tube	Protection Band
Ω/cm^2	**10^4 to 10^{11}**	**10^4 to 10^{11}**	**10^4 to 10^{11}**	**10^4 to 10^{11}**	**10^4 to 10^{11}**	**10^4 to 10^{11}**

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Datasheet Revision History

Version	Date	Description	Item
00	2023/7/7	Modify	Features on P1, 2 Ordering Information on P2 Functional Pin Description on P3, 4 Absolute Maximum Ratings on P5 Electrical Characteristics on P6 to 16 Typical Application Circuit on P20 Typical Operating Characteristics on P21 Register Description on P22, 23, 24, 25, 26, 28, 39, 42, 51 Application Information on P59, 60, 73, 74, 75, 76, 77
01	2024/1/18	Modify	General Description on P1 Ordering Information on P2 Recommended Operating Conditions on P6 Electrical Characteristics on P10 Packing Information on P83, 84, 85, 86